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August 2013

FAN54300 — USB-Compliant, Dual-Power Input, Single-Cell, Li-Ion Switching Charger with USB-OTG Boost Regulator

Features

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Accepts USB or Dedicated Power Input Source
- 5 V, 300 mA Boost Mode for USB OTG from 2.5 to 4.5 V Battery Input
- Charge Voltage Accuracy: ±0.5% at T_A=25°C
  ±1% from T_A=0 to 125°C
- ±5% USB Input Current Regulation Accuracy
- ±5% Charge Current Regulation Accuracy
- 20 V Absolute Maximum Input Voltage
- 9.5 V Maximum Input Operating Voltage on VIN Pin, 6.5 V Maximum on VBUS Pin
- Up to 1.5 A Maximum Charge Rate
- Programmable Charge and Mode through High-Speed I^{2}C Interface (3.4 Mb/s) with Fast Mode Plus Compatibility
  - Input Current
  - Fast-Charge / Termination Current
  - Charger Voltage
  - Safety Timer
  - Termination Enable
- 3 MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint, 1 μH, External Inductors
- Safety Timer with Reset Control
- Weak Input Sources Accommodated by Reducing Charging Current to Maintain Minimum V_{BUS} Voltage
- Low Reverse Leakage from Battery Drain to VBUS or VIN
- Programmable LED Drive for Charge Indication
- Register and Slave Addresses Compatible with FAN540X and FAN542X Families

Description

The FAN54300 combines two highly integrated switch-mode chargers and a boost regulator to minimize single-cell Li-Ion charging time from a USB and/or auxiliary power source.

Charging parameters and operating modes are programmable through an I^{2}C Bus® interface that operates up to 3.4 Mbps. The charger and boost regulator circuits switch at 3 MHz to minimize the size of the external passive components.

The FAN54300 provides battery charging in three phases: conditioning, constant current, and constant voltage.

To ensure USB compliance and minimize charging time, the USB input current is limited to the value set through the I^{2}C host. Charge termination is determined by a programmable minimum current level. A safety timer with reset control provides a safety backup for the I^{2}C host.

The IC automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode, with leakage from the battery to the input prevented. Charge status is reported back to the host through the I^{2}C port. Charge current is reduced when the die temperature reaches 120°C.

The FAN54300 can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery.

The FAN54300 is available in a 30-bump, 0.4 mm pitch, wafer-level, chip-scale package (WLCSP).

Applications

- Cell Phones, Smart Phones, PDAs
- Digital Cameras
- Portable Media Players

Ordering Information

Part Number	Temperature Range	Package	Packing
FAN54300UCX	-40 to 85°C	30-Ball, WLCSP, 5x6 Array, 0.4mm Pitch, 586 μm Package Height	Tape and Reel

Table 1. Feature Summary

Part Number	Automatic Charge	Battery Absent Charge
FAN54300	Yes	No

Typical Application

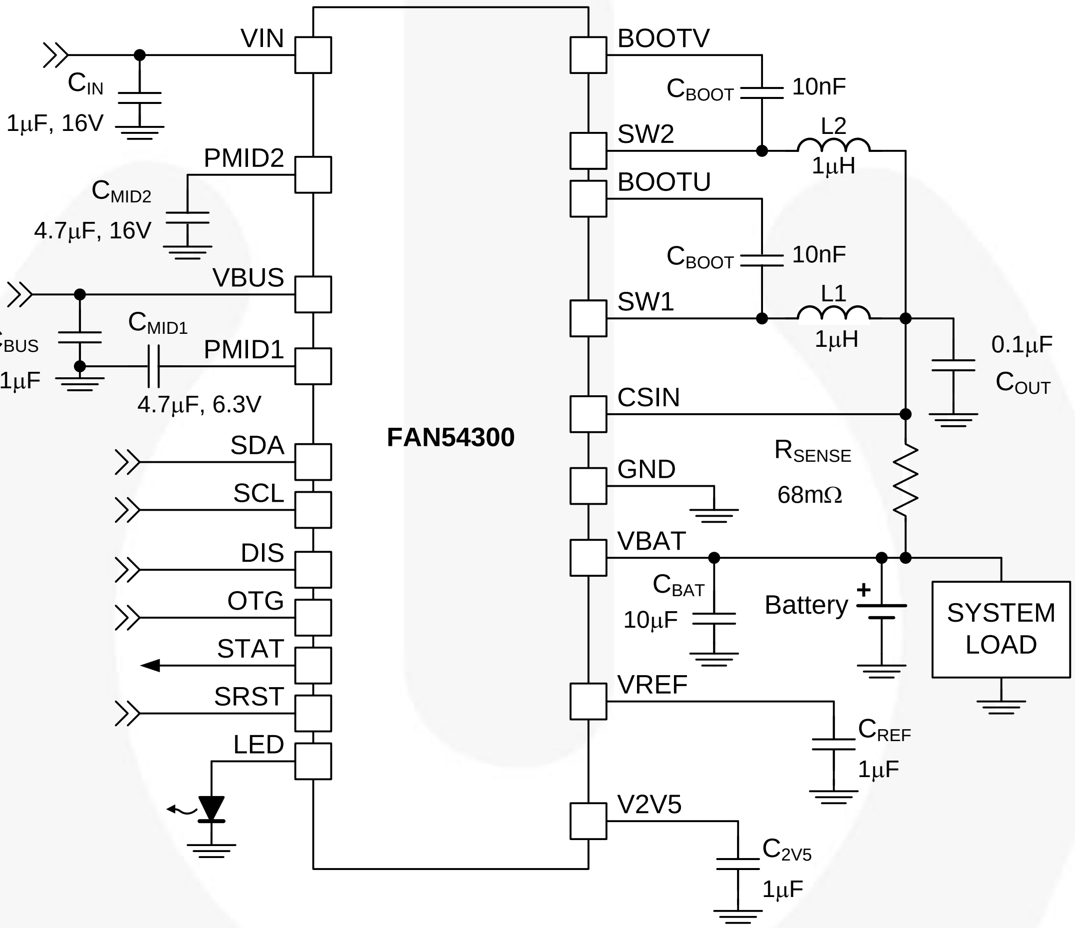

Figure 1. Typical Application

Block Diagrams

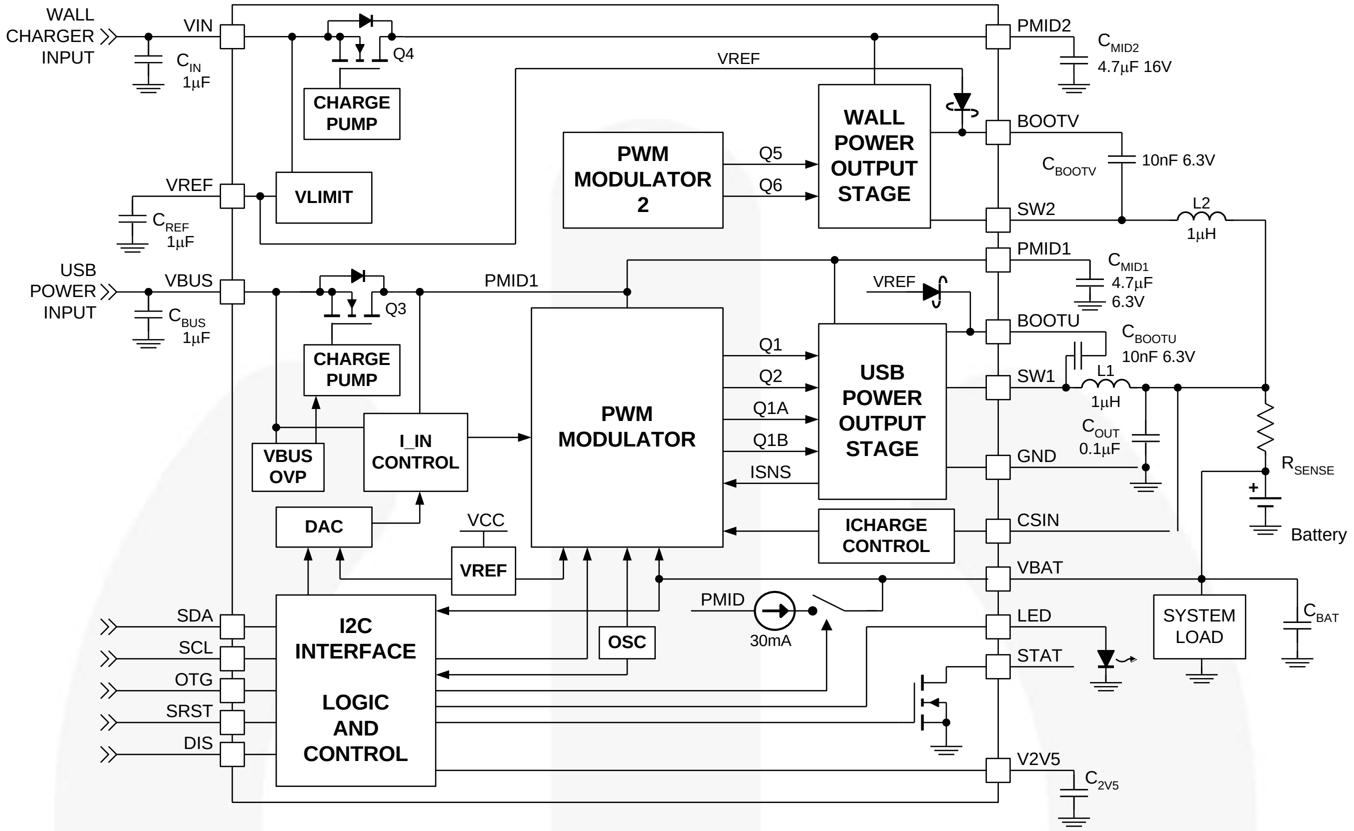

Figure 2. IC and System Block Diagram

Table 2. Recommended External Components

Component	Description	Vendor	Parameter	Typ.	Units
L1, L2:	Charge Currents to 1 A: 1 µH, 20%, 1.3 A, 2016	Murata: LQM2MPN1R0M	L	1.0	µH
			DCR	85	mΩ
	Charge Currents Above 1 A: 1 µH, 20%, 1.6 A, 2520	Murata: LQM2HPN1R0M	L	1.0	µH
			DCR	55	mΩ
C_{BAT}	10 µF, 20%, 6.3 V, X5R, 0603	Murata: GRM188R60J106M	C	10	µF
$C_{MID1,2}$	4.7 µF, 10%, 16 V, X5R, 0805	Murata: GRM21BR61C475K	C	4.7	µF
C_{IN}, C_{BUS}	1.0 µF, 10%, 16 V, X5R, 0603	Murata GRM188R61E105K	C	1.0	µF
C_{BOOT}	10 nF, 10%, 6.3 V, X5R, 0201	Murata GRM033R70J103K	C	10	nF
C_{OUT}	0.1 µF, 10%, 6.3 V, X5R, 0201	Murata GRM033R60J104K	C	0.1	µF
C_{2V5}, C_{REF}	1µF, 10%, 6.3 V, X5R, 0402	Murata GRM155R60J105M	C	1.0	µF

Block Diagrams (Continued)

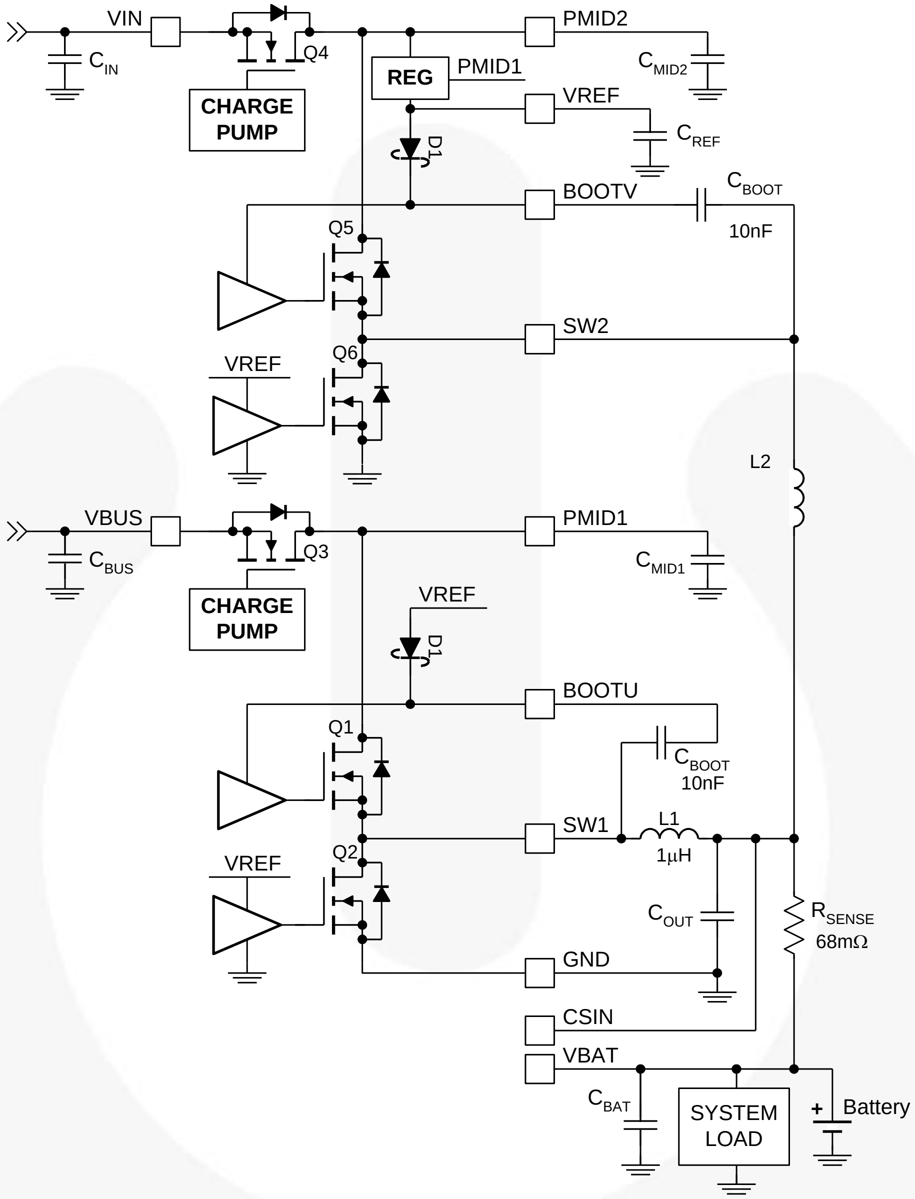

Figure 3. Power Output

Pin Configuration

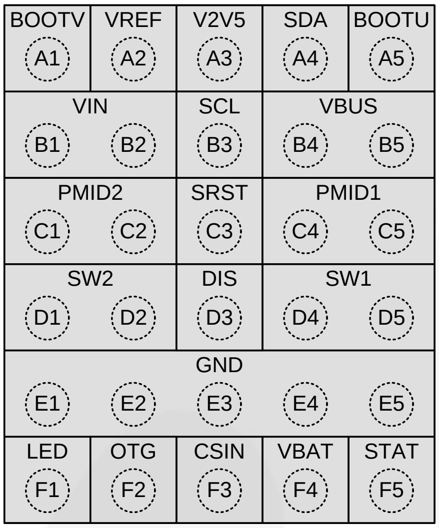

Figure 4. Pin Assignments (Top View)

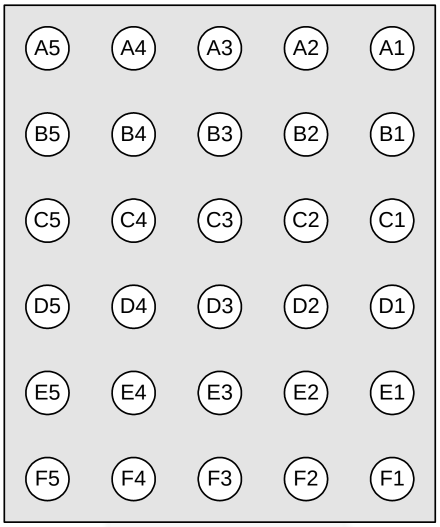

Figure 5. Pin Assignments (Bottom View)

Pin Definitions

Pin #	Name	Description
A1	BOOTV	**BOOT**. High-side NMOS driver supply. Connect a 10nF capacitor from SW2 to this pin.
A2	VREF	**Bias Regulator Output**. Connect to a 1 μF capacitor to PGND. This pin supplies the internal gate drive and power supply to the IC while charging. Up to 5 mA of current can be provided from this pin to drive external circuits. This pin is active when either V_{IN} or V_{BUS} are above V_{BAT}.
A3	V2V5	**2.5 V Regulator**. Connect to a 1 μF capacitor to PGND. Up to 5 mA can be provided from this pin to drive external circuits. This regulator is powered only when VIN is connected.
A4	SDA	**I^{2}C Interface Serial Data**. This pin should not be left floating.
A5	BOOTU	**BOOT**. High-side NMOS driver supply. Connect a 10 nF capacitor from SW1 to this pin.
B1, B2	VIN	**Charger Input Voltage**. Bypass with a minimum of 1 μF, 16 V capacitor to GND.
B3	SCL	**I^{2}C Interface Serial Clock**. This pin should not be left floating.
B4, B5	VBUS	**USB Input Voltage**. Bypass with a 1 μF, 16 V capacitor to GND.
C1, C2	PMID2	**Power Input Voltage for VIN Power Source**. Power input to the charger regulator, bypass point for the VIN input current sense, and high-voltage input switch. Bypass with a minimum of 4.7 μF, 16 V capacitor to PGND.
C3	SRST	**Safety Reset**. When LOW, both safety registers are reset to their default values. When HIGH, the safety registers reset when V_{BAT} drops below V_{SHORT}.
C4, C5	PMID1	**Power Input Voltage for VBUS Power Source**. Power input to the VBUS switching charger regulator, bypass point for the VBUS input current sense, and high-voltage input switch. Bypass with a minimum of 4.7 μF, 6.3 V capacitor to PGND.
D1, D2	SW2	**Switching Node for VIN Charger**. Connect to the output inductor.
D3	DIS	**Charge Disable**. When this pin is HIGH, charging is disabled and no timers are reset. When LOW, charging is controlled by the I^{2}C registers. This pin does not affect the 32-second timer.
D4, D5	SW1	**Switching Node for VBUS Charger and OTG Boost**. Connect to the output inductor.
E1–E5	GND	**Ground**. Power return for gate drive and power transistors as well as IC signal ground. The connection from this pin to the bottoms of the C_{PMID} capacitors should be as short as possible.
F1	LED	**Light Emitting Diode Output**. Up to 5 mA current source drive from the active PMID indicates the battery is charging.

Pin #	Name	Description
F2	OTG	**On The Go**. When unattended charging is indicated, the level on this pin sets the I_{BUS} current limit. This pin is also used to put the IC into Boost Mode.
F3	CSIN	**Current-Sense Input**. Connect to sense resistor in series with the battery. The IC uses this node to sense current into the battery. Bypass this pin with a 0.1 μF capacitor to PGND.
F4	VBAT	**Battery Voltage**. Connect to the positive (+) terminal of the battery pack. Bypass with a 10 μF capacitor to PGND.
F5	STAT	**Status**. Open-drain output indicating charge status. The IC pulls this pin LOW when charging is in process.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V_{BUS}	VBUS Voltage	Continuous	–1.4	20.0	V
		Pulsed, 100 ms Maximum Non-Repetitive	–2.0		
V_{IN}	VIN Voltage		–2.0	20.0	V
V_{BOOTU}	BOOTU Voltage		-0.7	20.0	V
V_{BOOTV}	BOOTV Voltage		-0.7	20.0	V
V_{PMID1}	PMID1 Voltage		–1.0	20.0	V
V_{SW1}	SW1 Voltage		–0.7	6.5	V
V_{PMID2}	PMID2 Voltage		–1.0	20.0	V
V_{SW2}	SW2 Voltage		–0.7	12.0	V
V_O	Other Pins		–0.3	6.5(1)	V
$\frac{dV_{BUS}}{dt}$	Maximum Rate of V_{BUS} Increase Above 5.5 V when IC Enabled			4	V/µs
$\frac{dV_{IN}}{dt}$	Maximum Rate of V_{IN} Increase Above 9.5 V when IC Enabled			4	V/µs
ESD	Electrostatic Discharge Protection Level	Human Body Model per JESD22-A114	2.0		kV
		Charged Device Model per JESD22-C101	1.5		kV
T_J	Junction Temperature		–40	+150	°C
T_{STG}	Storage Temperature		–65	+150	°C
T_L	Lead Soldering Temperature, 10 Seconds			+260	°C

Note:

1. Lesser of 6.5 V or V_{REF} + 0.3 V.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Units
V_{BUS}	VBUS Supply Voltage	4	6	V
V_{IN}	VIN Supply Voltage	4.0	9.5	V
T_A	Ambient Temperature	–30	+85	°C
T_J	Junction Temperature	0	+125	°C

Thermal Properties

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature $T_{J(max)}$ at a given ambient temperate T_A.

Symbol	Parameter	Typical	Unit
θ_{JA}	Junction-to-Ambient Thermal Resistance	60	°C/W
θ_{JB}	Junction-to-PCB Thermal Resistance	20	°C/W

Electrical Specifications

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A, V_{BUS} or V_{IN} = 5.0 V, HZ1, HZ2, OPA_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8 V. Typical values are for T_J = 25°C.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Power Supplies						
I_{VBUS}	VBUS Current	PWM Switching, Open Battery, TE=0		33		mA
		PWM Not Switching ($V_{BAT} > V_{OREG}$)		3.6		mA
		0°C < T_J < 85°C, HZ1 = 1, $V_{BAT} > V_{LOWV}$		350	500	µA
		0°C < T_J < 85°C, HZ1 = 1, $V_{BAT} <$ V_{LOWV}, 32S Mode		350	500	µA
I_{VIN}	VIN Current	PWM Switching, Open Battery, TE=0		33		mA
		PWM Not Switching ($V_{BAT}>V_{OREG}$)		2.6		mA
		0°C < T_J < 85°C, HZ2 = 1, $V_{IN} > V_{LOWV}$		350	500	µA
		0°C < T_J < 85°C, HZ2 = 1, $V_{IN} < V_{LOWV}$, 32S Mode		350	500	µA
I_{BAT}	Battery Discharge Current in High-Z Mode	0°C < T_J < 85°C, HZ1=HZ2 = 1 or DIS=1, V_{BAT} = 4.2 V			20	µA
		0°C < T_J < 85°C, V_{BAT} = 4.2 V, V_{IN} = V_{BUS} = Open or GND, HZ1=HZ2=1, SDA = SCL = 1.8 V, No I^2C Traffic			30	µA
Charger Voltage Regulation						
V_{OREG}	Charge Voltage Range		3.5		4.4	V
	Charge Voltage Accuracy	T_A = 25°C	–0.5		+0.5	%
		T_J = 0 to 125°C	–1		+1	%
Charging Current Regulation						
I_{OCHRG}	Output Charge Current Range	$V_{LOWV} < V_{BAT} < V_{OREG}$, $V_{BUS} > V_{SLP}$, R_{SENSE} = 68 mΩ	550		1500	mA
	Charge Current Accuracy Across R_{SENSE}	20 mV ≤ V_{IREG} ≤ 40 mV	92	97	102	% of Setting
		V_{IREG} > 40 mV	94	97	100	
Weak-Battery Detection						
V_{LOWV}	Weak-Battery Threshold Accuracy	3.4 ≤ V_{LOWV} ≤ 3.7	-5		+5	%
	Weak Battery Deglitch Time	Rising Voltage, 2 mV Overdrive		30		ms
Logic Levels: DIS, SDA, SCL, OTG						
V_{IH}	HIGH-Level Input Voltage		1.05			V
V_{IL}	LOW-Level Input Voltage				0.4	V
I_{IN}	Input Bias Current	Input Tied to GND or V_{BAT}		0.01	1.00	µA
Charge Termination Detection						
$I_{(TERM)}$	Termination Current Range	$V_{BAT} > V_{OREG} – V_{RCH}$, $V_{BUS} > V_{SLP}$, R_{SENSE} = 68 mΩ	50		400	mA
	Termination Current Accuracy	[V_{CSIN} – V_{BAT}] from 3 mV to 20 mV	–25%		+25%	
		[V_{CSIN} – V_{BAT}] from 20 mV to 40 mV	–5%		+5%	
	Termination Current Deglitch Time	2 mV Overdrive		30		ms

Continued on the following page…

Electrical Specifications (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A, V_{BUS} or V_{IN} = 5.0 V, HZ1, HZ2, OPA_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8V. Typical values are for T_J = 25°C.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
VBUS Input Power Source Detection						
$V_{BUS(MIN)1}$	V_{BUS} Input Voltage Rising	To Start V_{BUS} Validation	4.20	4.30	4.40	V
$V_{BUS(MIN)2}$	Min. V_{BUS} to Pass Validation	During V_{BUS} Validation Period	4.00	4.08	4.15	V
$V_{BUS(MIN)3}$	Min. V_{BUS} During Charge	During Charging	3.64	3.71	3.78	V
t_{VBUS_VALID}	V_{BUS} Validation Time			30		ms
$VBUS_{LOAD}$	V_{BUS} Load	V_{BUS} = 5 V, Applied at V_{BUS} Validation		50		mA
VIN Input Power Source Detection						
$V_{IN(MIN)1}$	V_{IN} Input Voltage Rising	To Start V_{IN} Validation	4.20	4.30	4.40	V
$V_{IN(MIN)2}$	Min. V_{IN} to Pass Validation	During V_{IN} Validation Period	4.00	4.08	4.15	V
$V_{IN(MIN)3}$	Min. V_{IN} During Charge	During Charging	3.64	3.71	3.78	V
t_{VBUS_VALID}	V_{IN} Validation Time			30		ms
VIN_{LOAD}	V_{IN} Load	V_{IN} = 5 V, Applied at V_{IN} Validation		50		mA
Input Current Limit						
I_{BUSLIM}	VBUS Input Current-Limit Threshold	I_{BUS} set to 100 mA	88	93	98	mA
		I_{BUS} set to 500 mA	450	475	500	
V_{2V5} 2.5V Linear Regulator						
V_{2V5}	2.5 V Regulator Output	I_{2V5} from 0 to 5 mA, V_{IN} > 4.75 V	2.35	2.50	2.65	V
	Current Limit		6	8		mA
V_{REF} Bias Generator						
V_{REF}	Bias regulator voltage	V_{IN} > $V_{IN(MIN)}$	3.5		6.0	V
	current limit		10	15		mA
Battery Recharge Threshold						
V_{RCH}	Recharge Threshold	Below $V_{(OREG)}$	100	120	150	mV
	Deglitch Time	VBAT falling below V_{RCH} threshold		130		ms
STAT Output						
$V_{STAT(OL)}$	STAT Output LOW	I_{STAT} = 10 mA			0.4	V
$I_{STAT(OH)}$	STAT High Leakage Current	V_{STAT} = 5 V			1	µA
LED Output						
$I_{LED(ON)}$	LED Output Current Accuracy	V_{LED} from 1.5 to 3.5 V, Max. (V_{REF},V_{BAT}) – V_{LED} > 100 mV	–30		+30	%
$I_{LED(OFF)}$	LED Off-State Leakage Current	V_{LED} = 0 V			1	µA
Battery Detection						
I_{DETECT}	Battery Detection Current Before Charge Complete (Sink Current)[(2)]	Begins After Termination Detected and $V_{BAT} \leq V_{OREG} - V_{RCH}$		–0.45		mA
t_{DETECT}	Battery Detection time			262		ms

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Electrical Specifications (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A, V_{BUS} or V_{IN} = 5.0 V, HZ1, HZ2, OPA_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8 V. Typical values are for T_J = 25°C.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Sleep Comparator						
V_{SLP}	Sleep Mode Entry Threshold, $V_{BUS} - V_{BAT}$ or $V_{IN} - V_{BAT}$	2.3 V $\leq V_{BAT} \leq V_{OREG}$, V_{PWRIN} Falling	0	90	160	mV
V_{SLP_EXIT}	Sleep Mode Exit Hysteresis	2.3 V $\leq V_{BAT} \leq V_{OREG}$		40		mV
	Deglitch Time for V_{BUS} Rising Above $V_{SLP} + V_{SLP\_EXIT}$	Rising Voltage		30		ms
Power Switches *(see Figure 3)*						
$R_{DS(ON)}$	Q3 On Resistance (VBUS to PMID1)	$IBUS_{(LIMIT)} \geq$ 500 mA		210	300	mΩ
	Q1 On Resistance (PMID1 to SW1)			110	225	
	Q2 On Resistance (SW1 to GND)			130	225	
	Q4 On Resistance (VIN to PMID2)			160	225	
	Q5 On Resistance (PMID2 to SW2)			110	225	
	Q6 On Resistance (SW2 to GND)			190	350	
Charger PWM Modulator						
f_{SW}	Oscillator Frequency		2.7	3.0	3.3	MHz
D_{MAX}	Maximum Duty Cycle				100	%
D_{MIN}	Minimum Duty Cycle			0		%
I_{SYNC}	Synchronous to Non-Synchronous Current Threshold(3)	Low-Side MOSFET Cycle-by-Cycle Current Limit		-120		mA
Boost Mode Operation (OPA_MODE = 1, HZ1 = 0)						
V_{BOOST}	Boost Output Voltage at VBUS	2.5 V < V_{BAT} < 4.5 V, 0-200 mA Load	4.80	5.05	5.17	V
		2.7 V < V_{BAT} < 4.5 V, 0-300 mA Load	4.77	5.05	5.17	
$I_{BAT(BOOST)}$	Boost Mode Quiescent Current	PFM Mode, V_{IN} = 3.6 V, I_{OUT} = 0		300	400	µA
$I_{LIMPK(BST)}$	Q2-Peak Current Limit		1160	1380	1550	mA
$V_{BAT(MAX)}$	Maximum Battery Input for Boost Operation	V_{BAT} Rising	4.7			V
	Hysteresis	V_{BAT} Falling		125		mV
$UVLO_{BST}$	Minimum Battery Voltage for Boost Operation	While Boost Active		2.42		V
		To Start Boost Regulator		2.58	2.70	
VBUS, VIN Load Resistance						
R_{VBUS}	VBUS to GND Resistance	Normal Operation	500	1000	1500	Ω
		V_{BUS} Validation	50	110	175	Ω
R_{VIN}	VIN to GND Resistance	Normal Operation	500	1000	1500	Ω
		V_{IN} Validation	50	110	175	Ω

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Electrical Specifications (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A, V_{BUS} or V_{IN} = 5.0 V, HZ1, HZ2, OPA_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8 V. Typical values are for T_J = 25°C.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Protection and Timers						
$VBUS_{OVP}$	VBUS Over-Voltage Shutdown	V_{BUS} Rising	6.12	6.31	6.50	V
	Hysteresis	V_{BUS} Falling		100		mV
VIN_{OVP}	VIN Over-Voltage Shutdown	V_{IN} Rising	9.5	10.0	10.5	V
	Hysteresis	V_{IN} Falling		100		mV
V_{SHORT}	Battery Short-Circuit Threshold	V_{BAT} Rising	2.00	2.05	2.10	V
	Hysteresis	V_{BAT} Falling		100		
I_{SHORT}	Short-Circuit Current	$V_{BAT} < V_{SHORT}$	30	40	50	mA
$T_{SHUTDWN}$	Thermal Shutdown Threshold(4)	T_J Rising		165		°C
	Hysteresis(4)	T_J Falling		10		
T_{CF}	Thermal Regulation Threshold(4)	Charge Current Reduction Begins		120		°C
t_{INT}	Detection Interval			2.1		s
t_{32SEC}	32-Second Timer(5)	32-Second Mode	21.0		31.5	s
t_{15MIN}	15-Minute Timer	15-Minute Mode	12.0	13.5	15.0	min
Δt_{LF}	Low Frequency Timer Accuracy	Charger Inactive	–25		25	%

Notes:

2. Refers to negative inductor current. At lower battery charging current, of about 20 mA, non-synchronous switching operation commences.
3. Q2 and Q6 always turn on for »60 ns and then turn off if the current is below I_{SYNC}.
4. Guaranteed by design.
5. This tolerance applies to all timers on the IC, including soft-start and deglitching timers.

I^{2}C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f_{SCL}	SCL Clock Frequency	Standard Mode			100	kHz
		Fast Mode			400	
		High-Speed Mode, $C_B \leq 100$ pF			3400	
		High-Speed Mode, $C_B \leq 400$ pF			1700	
t_{BUF}	Bus-Free Time between STOP and START Conditions	Standard Mode		4.7		μs
		Fast Mode		1.3		
$t_{HD;STA}$	START or Repeated START Hold Time	Standard Mode		4		μs
		Fast Mode		600		ns
		High-Speed Mode		160		ns
t_{LOW}	SCL LOW Period	Standard Mode		4.7		μs
		Fast Mode		1.3		μs
		High-Speed Mode, $C_B \leq 100$ pF		160		ns
		High-Speed Mode, $C_B \leq 400$ pF		320		ns
t_{HIGH}	SCL HIGH Period	Standard Mode		4		μs
		Fast Mode		600		ns
		High-Speed Mode, $C_B \leq 100$ pF		60		ns
		High-Speed Mode, $C_B \leq 400$ pF		120		ns
$t_{SU;STA}$	Repeated START Setup Time	Standard Mode		4.7		μs
		Fast Mode		600		ns
		High-Speed Mode		160		ns
$t_{SU;DAT}$	Data Setup Time	Standard Mode		250		ns
		Fast Mode		100		
		High-Speed Mode		10		
$t_{HD;DAT}$	Data Hold Time	Standard Mode	0		3.45	μs
		Fast Mode	0		900	ns
		High-Speed Mode, $C_B \leq 100$ pF	0		70	ns
		High-Speed Mode, $C_B \leq 400$ pF	0		150	ns
t_{RCL}	SCL Rise Time	Standard Mode	$20+0.1C_B$		1000	ns
		Fast Mode	$20+0.1C_B$		300	
		High-Speed Mode, $C_B \leq 100$ pF		10	80	
		High-Speed Mode, $C_B \leq 400$ pF		20	160	
t_{FCL}	SCL Fall Time	Standard Mode	$20+0.1C_B$		300	ns
		Fast Mode	$20+0.1C_B$		300	
		High-Speed Mode, $C_B \leq 100$ pF		10	40	
		High-Speed Mode, $C_B \leq 400$ pF		20	80	
t_{RDA} t_{RCL1}	SDA Rise Time Rise Time of SCL after a Repeated START Condition and after ACK Bit	Standard Mode	$20+0.1C_B$		1000	ns
		Fast Mode	$20+0.1C_B$		300	
		High-Speed Mode, $C_B \leq 100$ pF		10	80	
		High-Speed Mode, $C_B \leq 400$ pF		20	160	

Continued on the following page…

I^2C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
t_{FDA}	SDA Fall Time	Standard Mode	$20+0.1C_B$		300	ns
		Fast Mode	$20+0.1C_B$		300	
		High-Speed Mode, $C_B \leq 100$ pF		10	80	
		High-Speed Mode, $C_B \leq 400$ pF		20	160	
$t_{SU;STO}$	Stop Condition Setup Time	Standard Mode		4		µs
		Fast Mode		600		ns
		High-Speed Mode		160		ns
C_B	Capacitive Load for SDA, SCL				400	pF

Timing Diagrams

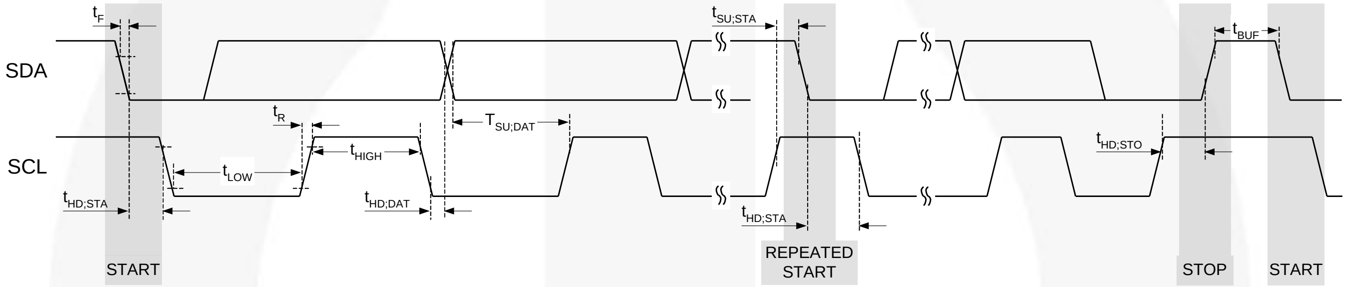
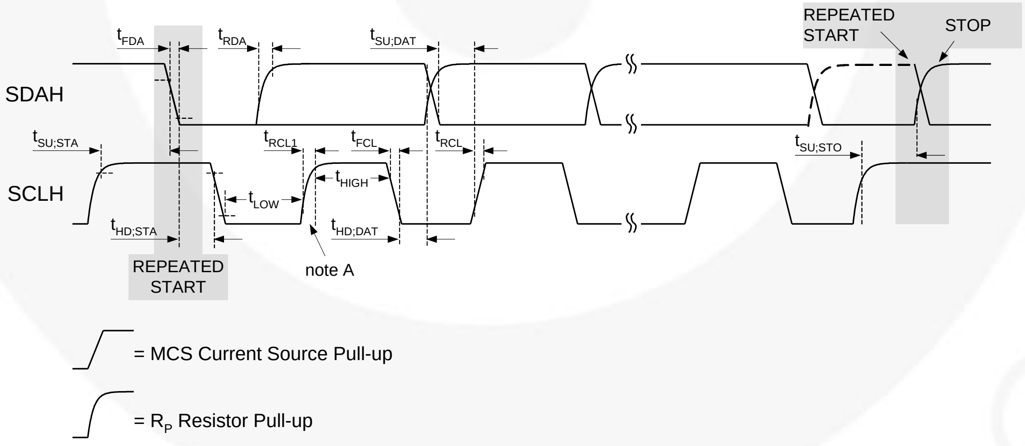


Figure 6. I^2C Interface Timing for Fast and Slow Modes



Note A: First rising edge of SCLH after Repeated Start and after each ACK bit.

Figure 7. I^2C Interface Timing for High-Speed Mode

VBUS Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, V_{OREG}=4.2 V, V_{BUS}=5.0 V, and T_A=25°C.

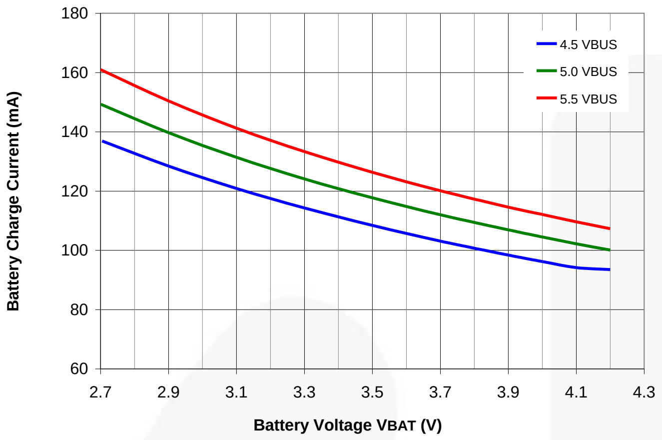


Figure 8. Battery Charge Current vs. V_{BUS} with I_{INLIM}=100 mA

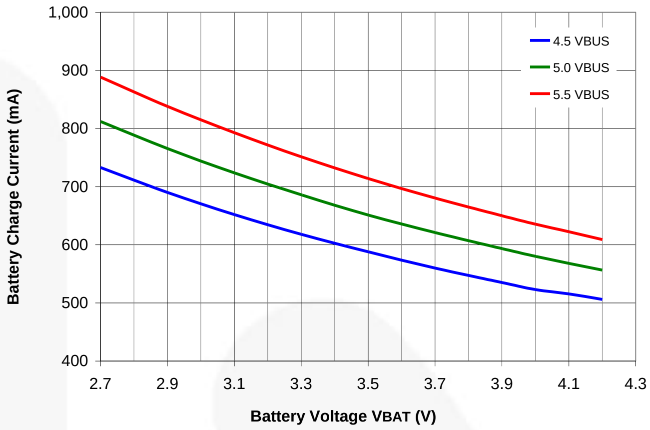


Figure 9. Battery Charge Current vs. V_{BUS} with I_{INLIM}=500 mA

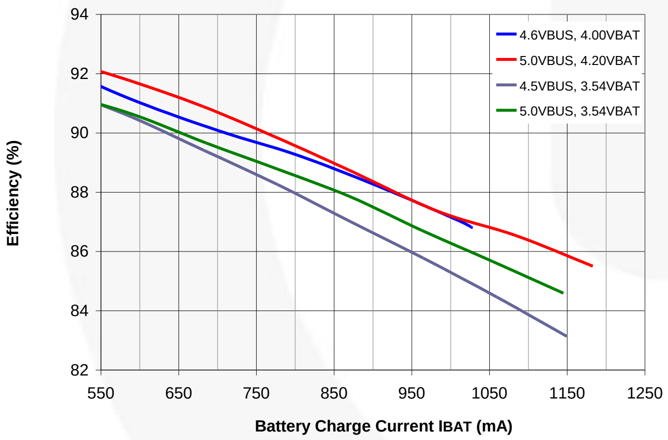


Figure 10. Charger Efficiency, No I_{INLIM}, $I_{OCHARGE}$=1250 mA

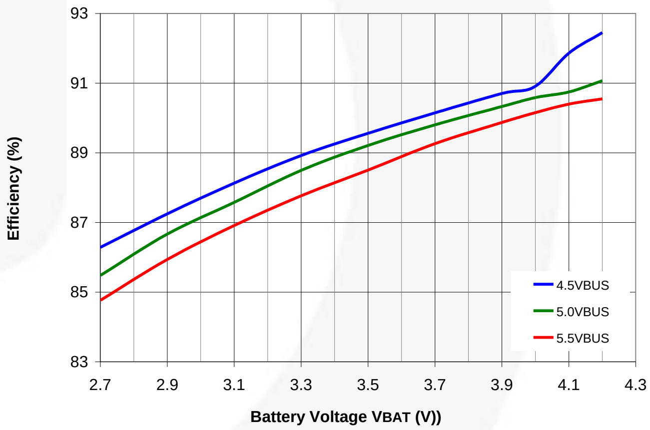


Figure 11. Charger Efficiency vs. V_{BUS}, I_{INLIM}=500 mA

VBUS Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, V_{OREG}=4.2 V, V_{BUS}=5.0 V, and T_A=25°C.

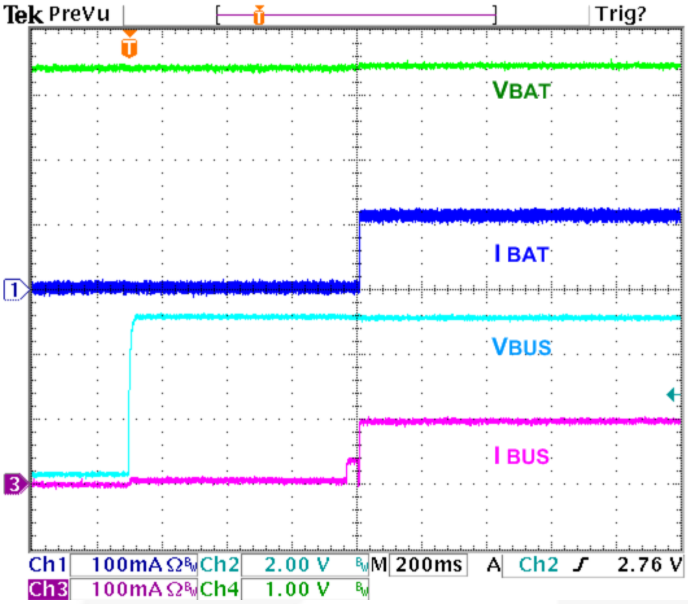


Figure 12. Auto-Charge Startup at V_{BUS} Plug-in, I_{INLIM}=100 mA, OTG=1, V_{BAT}=3.4 V

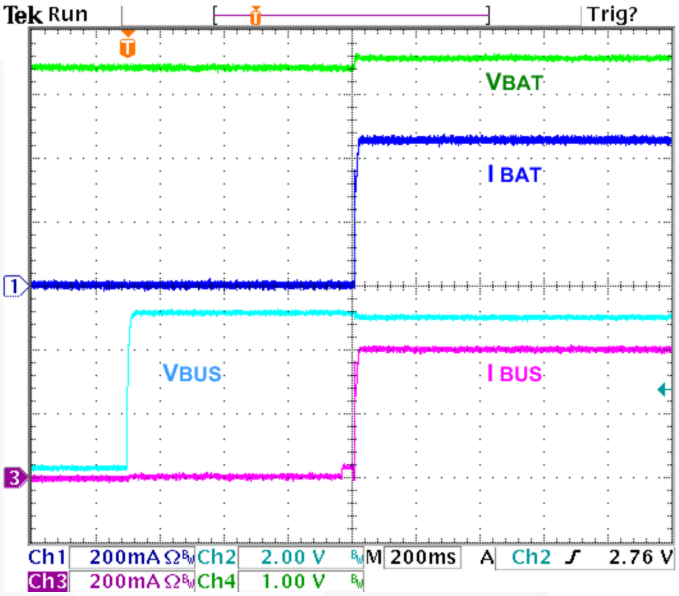


Figure 13. Auto-Charge Startup at V_{BUS} Plug-in, I_{INLIM}=500 mA, OTG=1, V_{BAT}=3.4 V

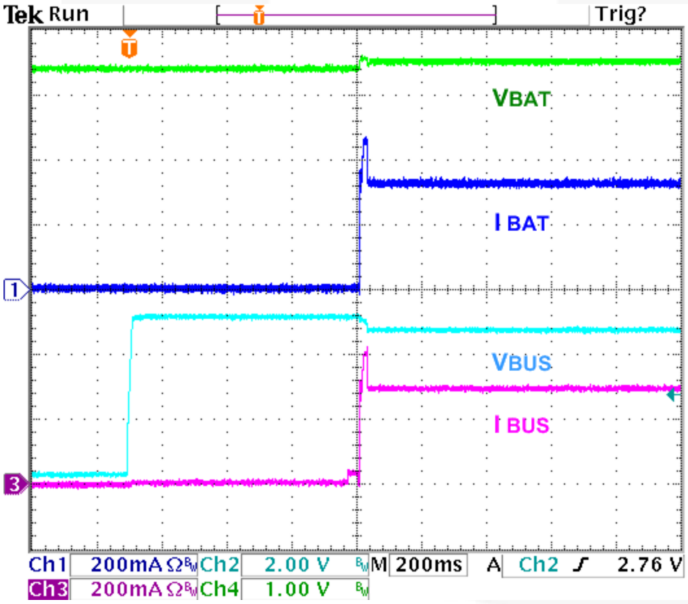


Figure 14. AutoCharge Startup with 300 mA Limited Charger / Adaptor, I_{INLIM}=500 mA, OTG=1, V_{BAT}=3.4 V

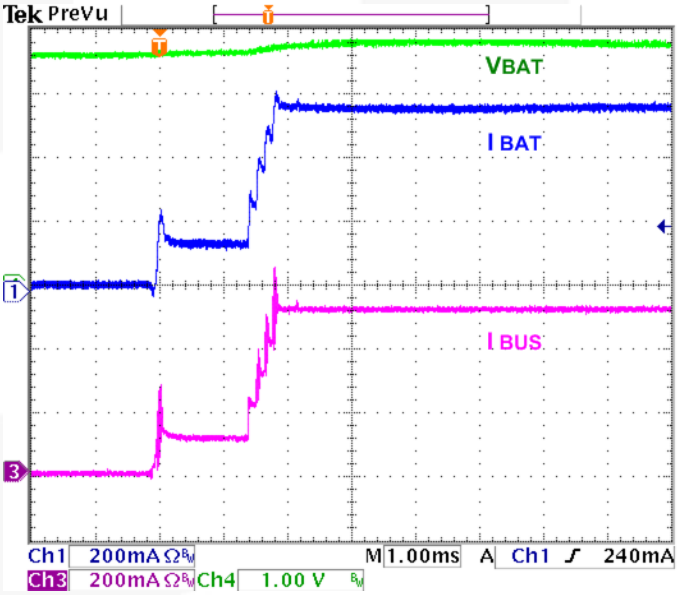


Figure 15. Charger Startup with HZ_MODE Bit Reset, I_{INLIM}=500 mA, $I_{OCHARGE}$=950 mA, V_{OREG}=4.2 V, V_{BAT}=3.6 V

VBUS Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, V_{OREG}=4.2 V, V_{BUS}=5.0 V, and T_A=25°C.

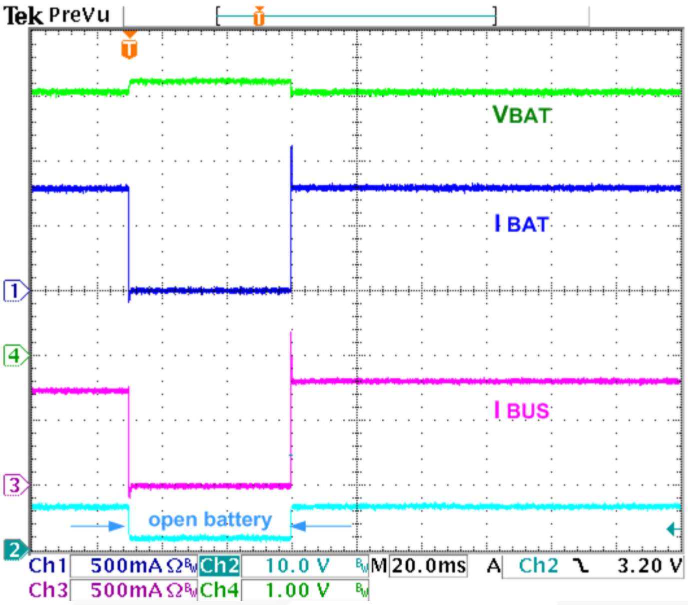


Figure 16. Battery Removal / Insertion during Charging, V_{BAT}=3.9 V, $I_{OCHARGE}$=950 mA, No I_{INLIM}, TE=0

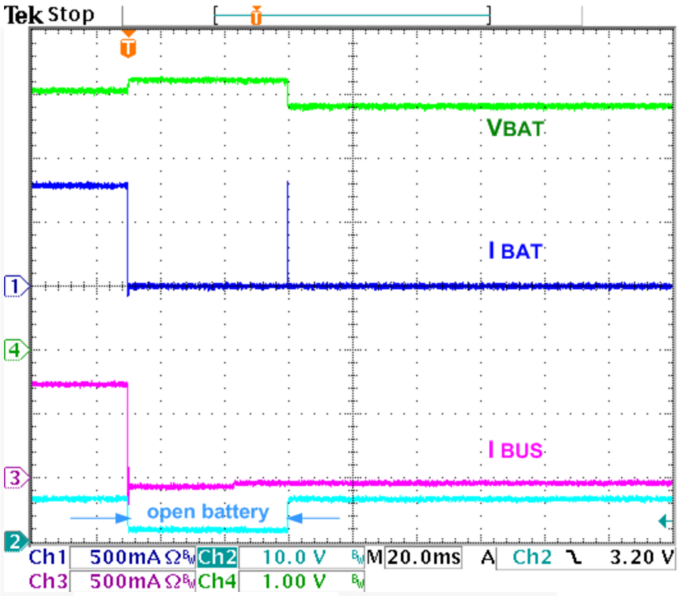


Figure 17. Battery Removal / Insertion during Charging, V_{BAT}=3.9 V, $I_{OCHARGE}$=950 mA, No I_{INLIM}, TE=1

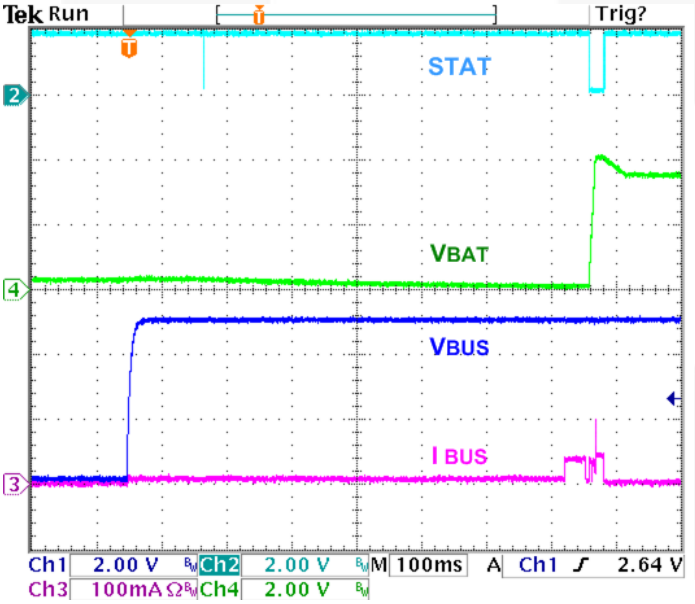


Figure 18. No Battery at V_{BUS} Power-up

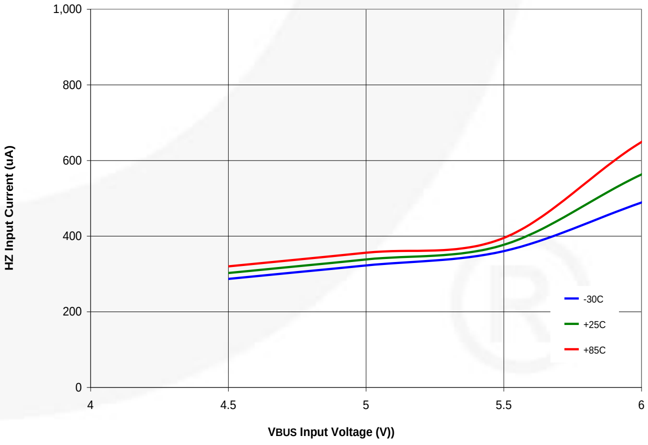


Figure 19. VBUS Current in High-Impedance Mode with Battery Open

VIN Charger Characteristics

Unless otherwise specified, circuit of Figure 1, V_{OREG} = 4.2 V, V_{IN} = 5.0 V, and T_A=25°C.

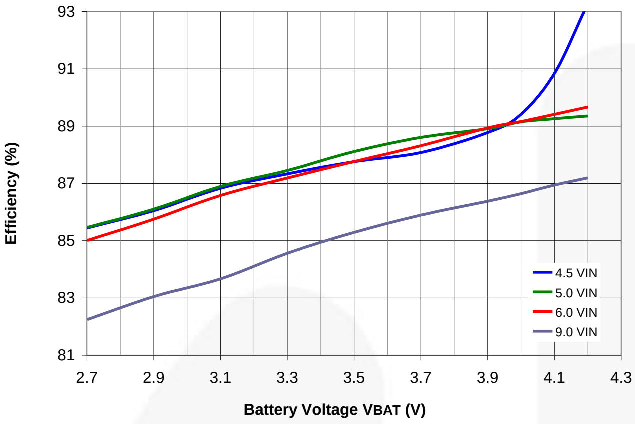


Figure 20. Charger Efficiency, $I_{OCHARGE}$=950 mA

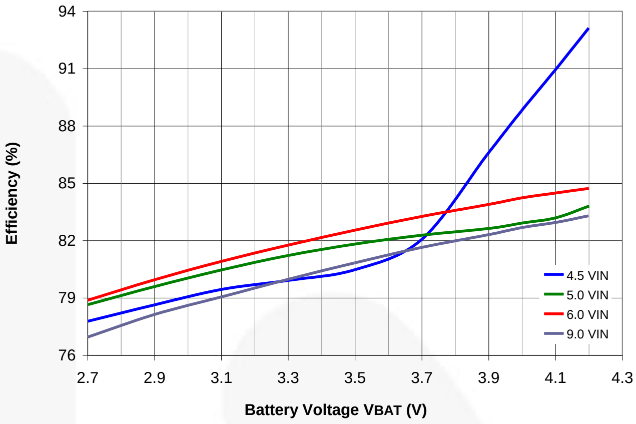


Figure 21. Charger Efficiency, $I_{OCHARGE}$=1550 mA

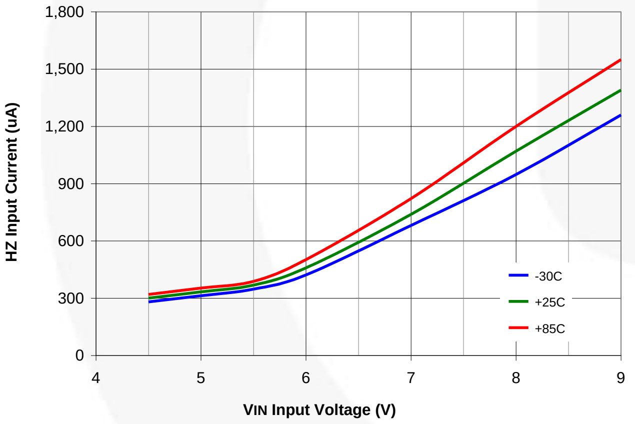


Figure 22. V_{IN} Current in High-Impedance Mode, V_{BAT}=3.6 V

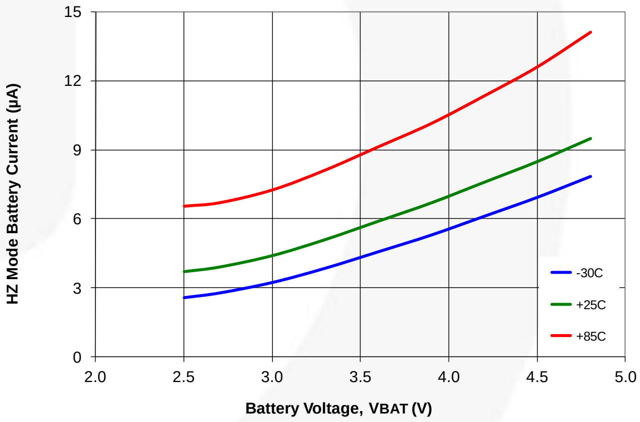


Figure 23. Battery Current in High-Impedance Mode, VBUS=Open, V_{IN}=Open

VIN Charger Characteristics

Unless otherwise specified, circuit of Figure 1, V_{OREG} = 4.2 V, V_{IN} = 5.0 V, and T_A=25°C.

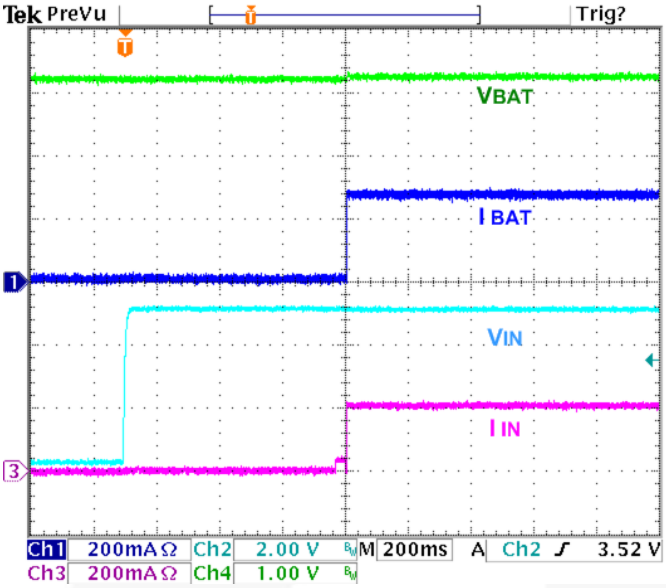


Figure 24. Auto-Charge Startup at V_{IN} Plug-in, V_{BAT}=3.2 V, IO_LEVELV = 1

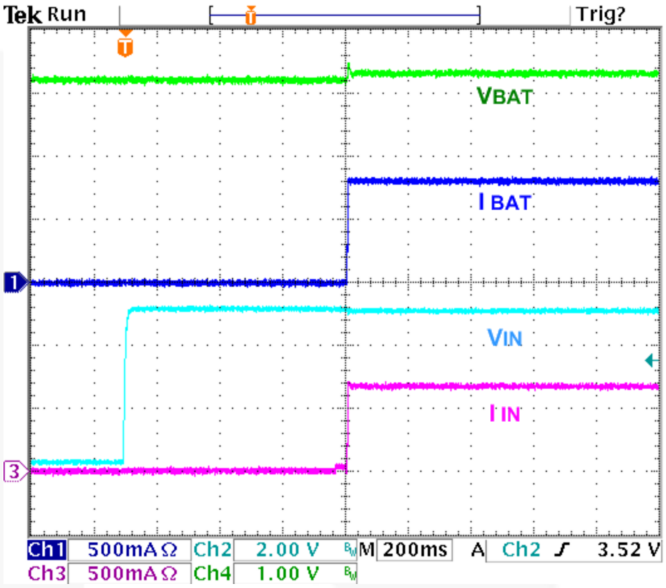


Figure 25. Auto-Charge Startup at V_{IN} Plug-in, V_{BAT}=3.2 V, $I_{OCHARGE}$=950 mA

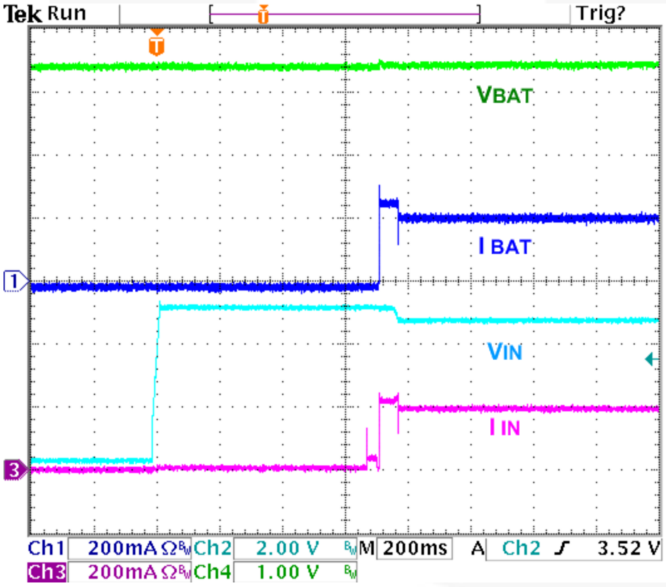


Figure 26. Auto-Charge Startup with 200 mA Limited Charger / Adaptor, V_{BAT}=3.4 V

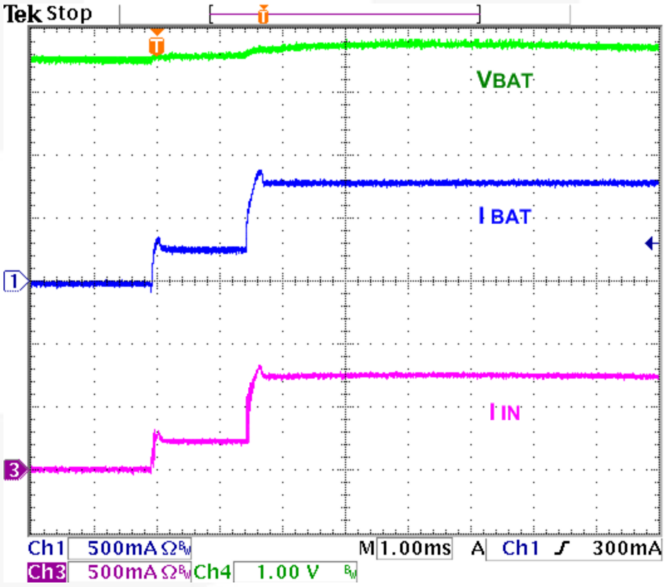


Figure 27. Charger Startup with HZ_MODE Bit Reset, $I_{OCHARGE}$=950 mA, V_{OREG}=4.2 V, V_{BAT}=3.6 V

VIN Charger Characteristics

Unless otherwise specified, circuit of Figure 1, V_{OREG} = 4.2 V, V_{IN} = 5.0 V, and T_A=25°C.

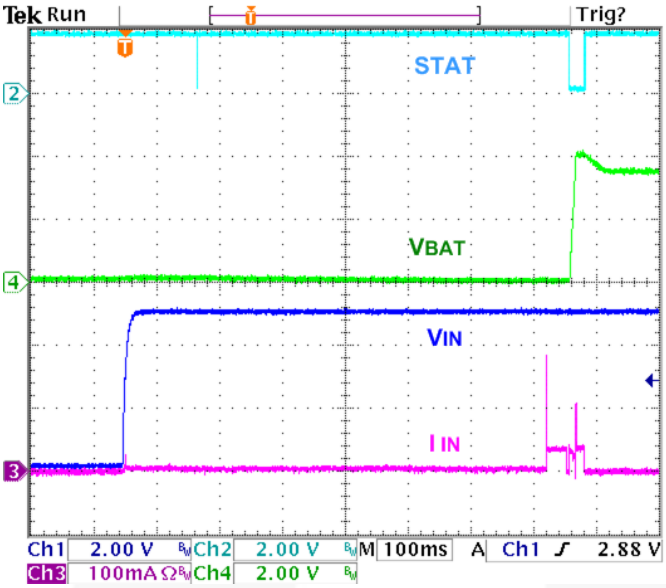


Figure 28. No Battery at V_{IN} Power-up

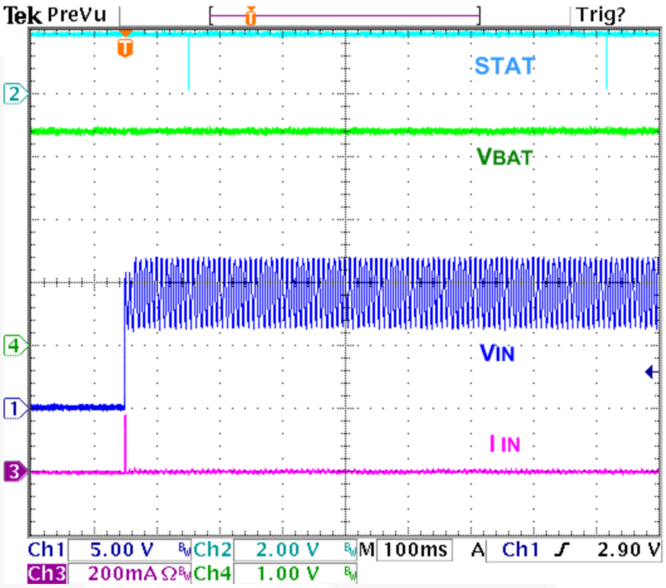


Figure 29. Non-Compliant Charger Rejection, V_{BAT}=3.4 V

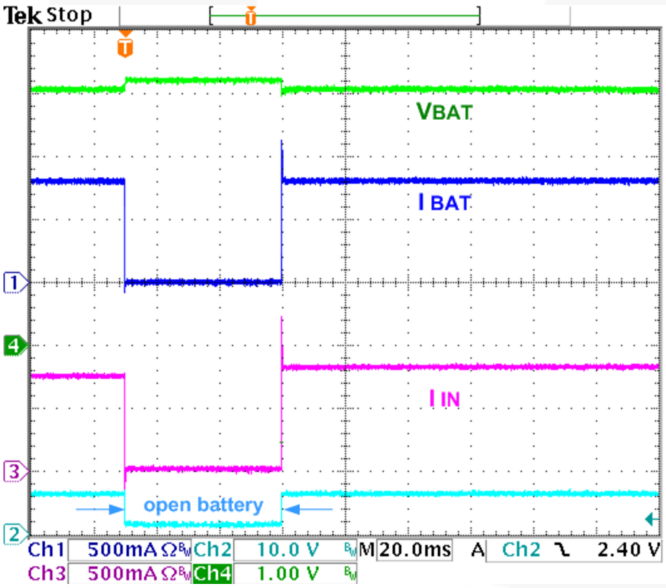


Figure 30. Battery Removal / Insertion During Charging, V_{BAT}=3.9 V, $I_{OCHARGE}$=950 mA, TE=0

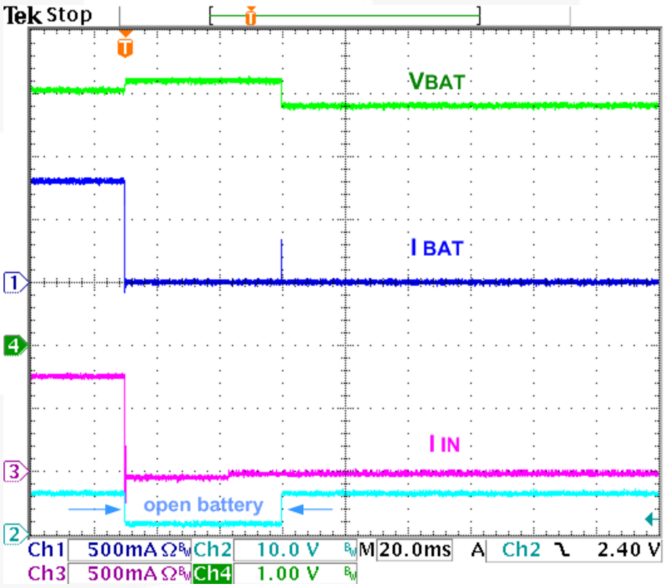


Figure 31. Battery Removal / Insertion During Charging, V_{BAT}=3.9 V, $I_{OCHARGE}$=950 mA, TE=1

Boost Mode Typical Characteristics

Unless otherwise specified, using the circuit of Figure 1, V_{BAT}=3.6 V, T_A=25°C.

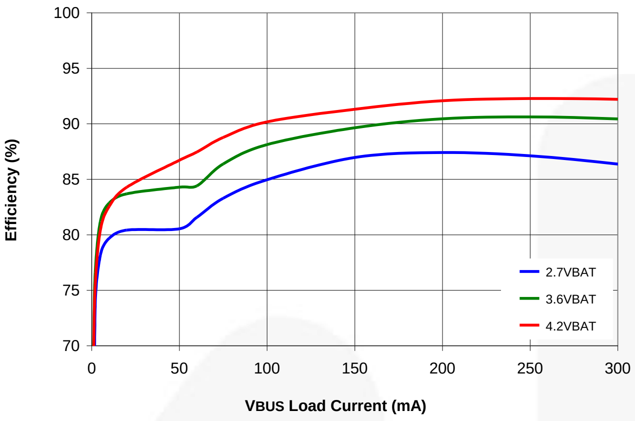


Figure 32. Efficiency vs. V_{BAT}

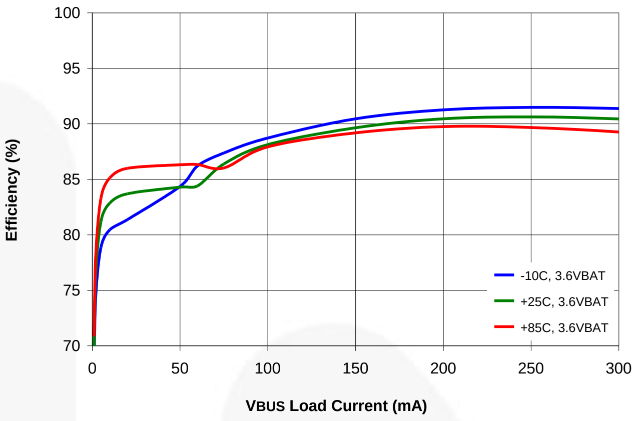


Figure 33. Efficiency Over Temperature

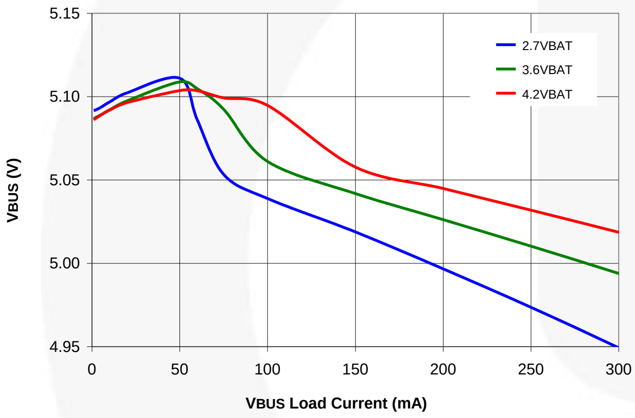


Figure 34. Output Regulation vs. V_{BAT}

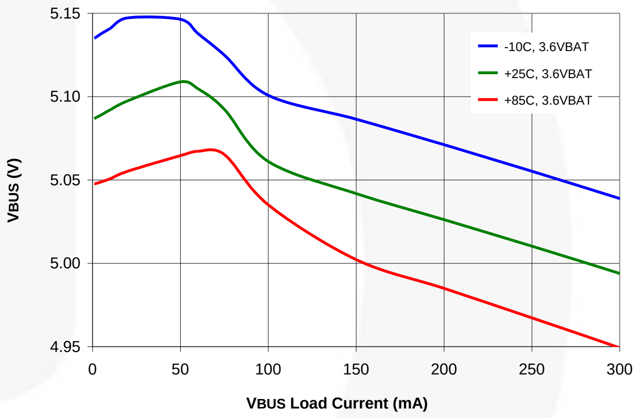


Figure 35. Output Regulation Over Temperature

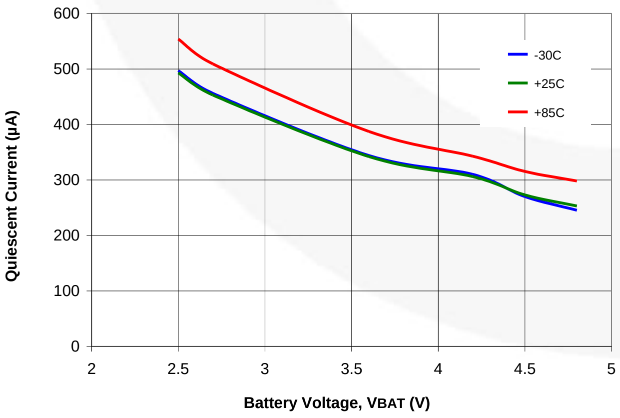


Figure 36. Quiescent Current

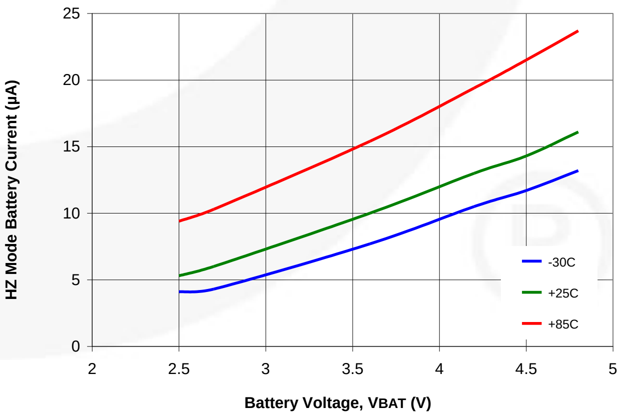


Figure 37. High-Impedance Mode Battery Current

Boost Mode Typical Characteristics

Unless otherwise specified, using the circuit of Figure 1, V_{BAT}=3.6 V, T_A=25°C.

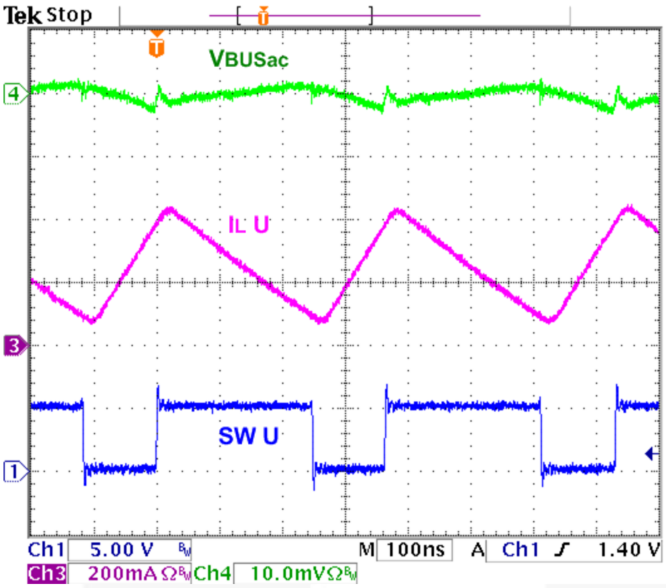


Figure 38. Boost PWM Waveform

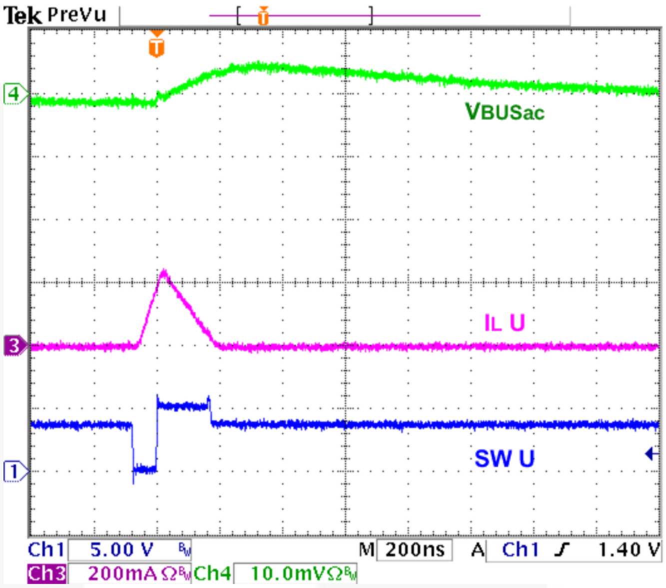


Figure 39. Boost PFM Waveform

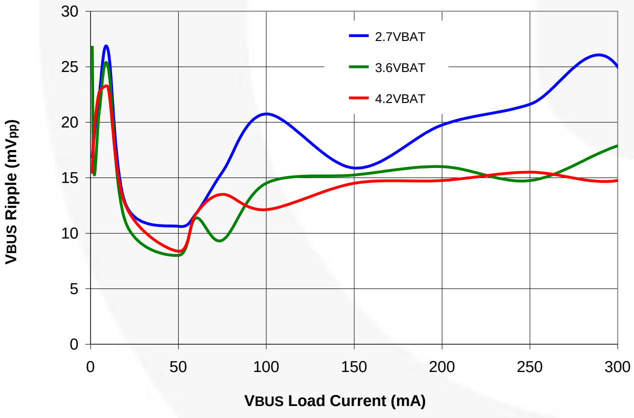


Figure 40. Output Ripple vs. V_{BAT}

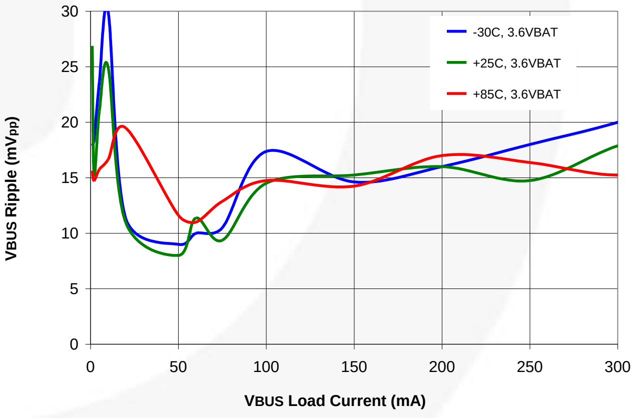


Figure 41. Output Ripple vs. Temperature

Boost Mode Typical Characteristics

Unless otherwise specified, using the circuit of Figure 1, V_{BAT}=3.6 V, T_A=25°C.

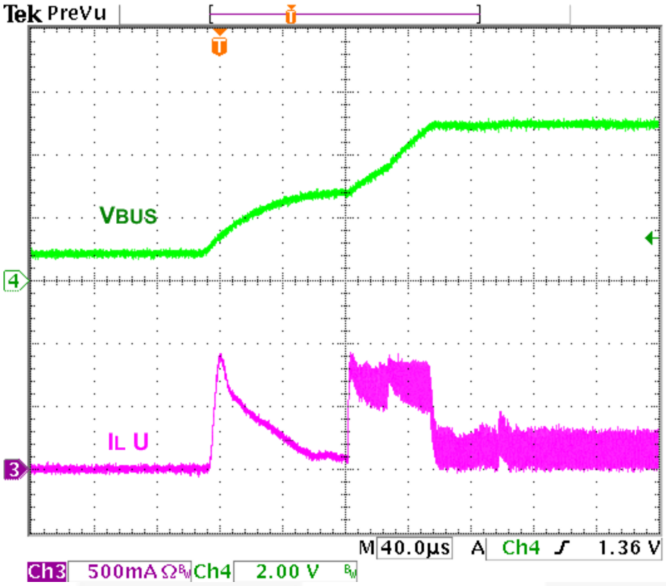


Figure 42. Startup, 3.6 V_{BAT}, 50 Ω Load, Additional 10 µF, X5R Across VBUS

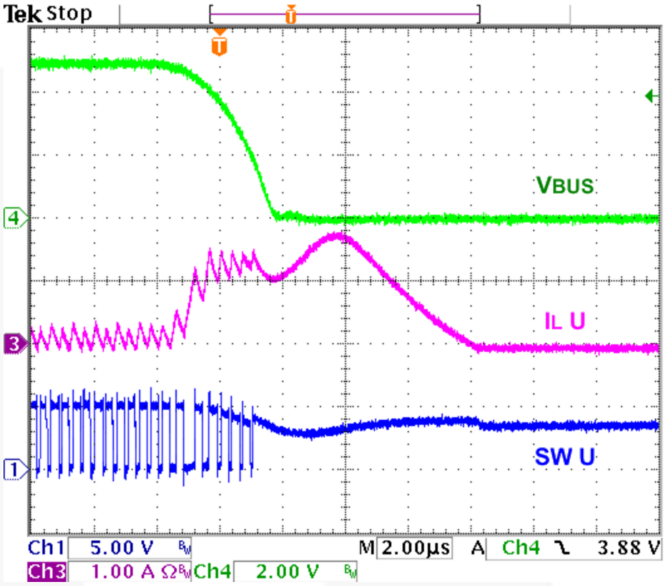


Figure 43. V_{BUS} Fault Response, 3.6 V_{BAT}

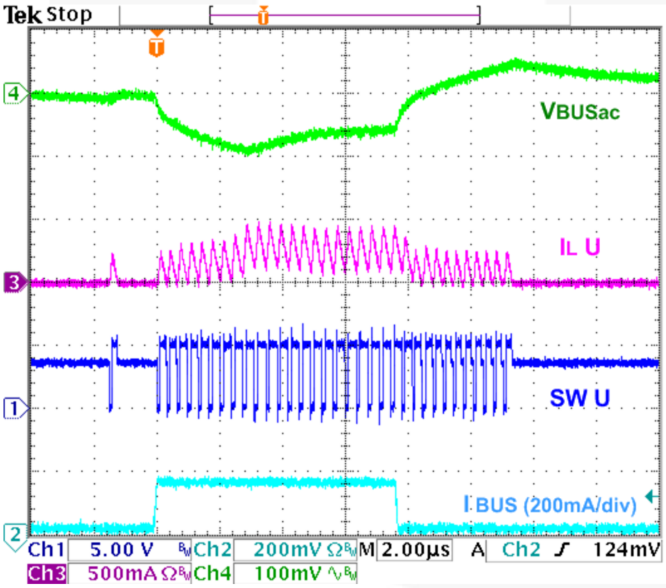


Figure 44. Load Transient, 5-155-5 mA, t_R=t_F=100 ns

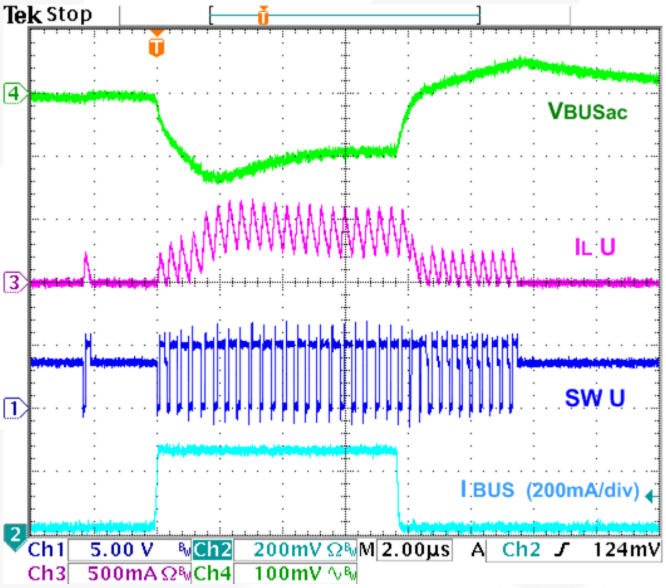


Figure 45. Load Transient, 5-255-5 mA, t_R=t_F=100 ns

Circuit Description / Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

The FAN54300 combines two highly integrated synchronous buck regulators for charging from two separate power sources. The IC also includes a synchronous boost regulator, which can supply 5 V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

In addition to its USB (VBUS) input, the FAN54300 allows a second power source (VIN) to be used for charging. This input source is typically a "wall wart" and can be up to 9.5 V input.

The FAN54300 has three operating modes:

- **Charge Mode**:
  Charges a single-cell Li-Ion or Li-polymer battery.
- **Boost Mode**:
  Provides 5 V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.
- **High-Impedance Mode**:
  Both the boost and charging circuits are off in this mode. Current flow from PWRIN (the charging power source) to the battery, or from the battery to PWRIN, are blocked in this mode. This mode consumes very little current from PWRIN or the battery.

When the IC is charging the battery from VIN, the boost regulator may be simultaneously enabled to supply 5 V for OTG peripherals.

Charge Mode

In Charge Mode, FAN54300 employs five regulation loops:

1. VBUS input current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I^2C interface
2. Charging current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.
3. Charge voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage rises, the battery's internal impedance and R_{SENSE} works in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R_{SENSE} drops below the I_{TERM} threshold.
4. Temperature: If the IC's junction temperature reaches 120°C, charge current is continuously reduced until the IC's temperature stabilizes at 120°C.
5. An additional loop limits the amount of drop on VBUS or VIN to a programmable voltage (V_{SP}) to accommodate current-limited wall chargers.

Input Source Selection

The FAN54300 selects the power source (PWRIN) for charging according to the following criteria.

Table 3. PWRIN: Charging Power Input Source Selection

V_{IN}	V_{BUS}	PWRIN
VALID	INVALID	V_{IN}
INVALID	VALID	V_{BUS}
VALID	VALID	V_{IN}

If charging is in progress with V_{BUS} and V_{IN} becomes valid, charging from VBUS stops and charging continues from V_{IN}. Charging stops if HZ_VIN is set when V_{IN} becomes valid while charging with V_{BUS}.

If VIN and VBUS are both connected and t_{15MIN} expires, both CE# bits are set. To reinitiate t_{15MIN} charging (autocharge) with a weak battery, both power sources must be unplugged, then a valid power source plugged in. If only one of the two connected sources are removed then connected with a weak battery, both CE# bits remain set.

Fault Reporting and Register Reset

All faults that occur during charging or boost are reported only in the STATUS register (R0) associated with the active charging source at the time of the fault. Any register reset that occurs due to t_{32SEC} overflow resets only the registers associated with the active charging source.

For example: Assume the IC is charging in 32-Second Mode with V_{IN} as a source. The processor stops setting TMR_RST, so t_{32SEC} expires. The IC then resets only the _V registers and goes into 15-Minute Mode charging with V_{IN}. A timer fault is enunciated, but reported in the CONTROL0_V register. CONTROL0_U is unaffected by this event. When the t_{15MIN} timer expires, the IC sets the CE#_V bit, but leaves the CE#_U bit unchanged.

Battery Charging Curve

If the battery voltage is below V_{SHORT}, a linear current source "pre-charges" the battery until V_{BAT} reaches V_{SHORT}. The PWM charging circuits are then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The FAN54300 is designed to work with a current-limited input source at PWRIN. During the current regulation phase of charging, PWRIN current limitations or the programmed charging current limit the amount of current available to charge the battery and power the system. The effect of input power limitations on I_{CHARGE} can be seen in Figure 47.

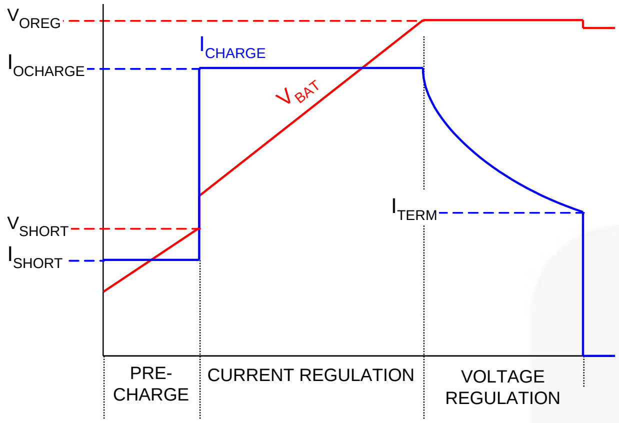


Figure 46. Charge Curve when PWRIN Limitations Don't Limit I_{CHARGE}

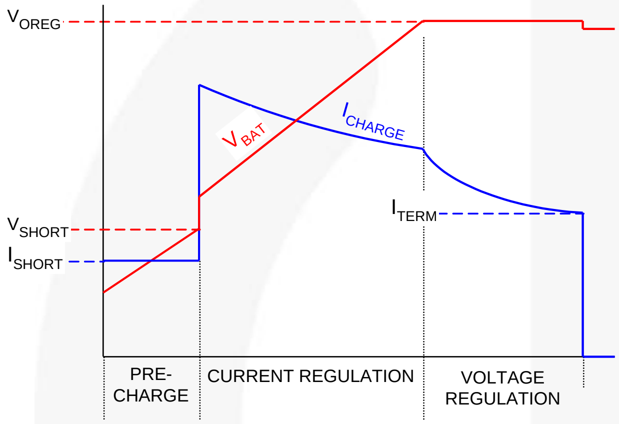


Figure 47. Charge Curve when PWRIN Limits I_{CHARGE}

PWRIN limitations are controlled either by:

- IBUSLIM: These bits set the maximum amount of current that the charger draws from VBUS; OR
- SP_CHARGER: For power-limited chargers, the FAN54300 limits current draw when the charging source drops to the voltage programmed by the SP_CHARGER bits. This allows "travel adapters" to be accommodated without host software overhead. The SP_CHARGER control loop applies to both VIN and VBUS.

Assuming V_{OREG} is programmed to the cell's fully charged "float" voltage, the current the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to VOREG declines and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting the TE bit.

Charger Programmability

Throughout this document, any parameter that ends in "U" applies when charging from V_{BUS} and any parameter ending in "V" applies when charging from V_{IN}. Parameters set with slave address D6 are applied when charging from V_{BUS}. Parameters set with slave address D4 are applied when charging from V_{IN}.

The following charging and input power control parameters can be programmed by the host through I^2C.

Table 4. Programmable Charging Parameters

Parameter	Charging Source	Name	Register
Output Voltage Regulation	Either	OREG	REG2[7:2]
Battery Charging Current Limit	V_{BUS}	ICHGU	REG4[6:4]
	V_{IN}	ICHGV	REG4[6:3]
Input Current Limit	V_{BUS}	IBUSLIM	REG1[7:6]
Charge Termination Limit	Either	ITERM	REG4[2:0]
Special Charger Minimum Voltage	Either	VSP	REG5[2:0]

The charger output or "float" voltage can be programmed by the OREG bits from 3.5 V to 4.44 V in 20 mV increments.

Table 5. OREG Bits (REG2 [7:2]) vs. Charger V_{OUT} (V_{OREG}) Float Voltage

Decimal	Hex	VOREG
0	00	3.50
1	01	3.52
2	**02**	**3.54**
3	03	3.56
4	04	3.58
5	05	3.60
6	06	3.62
7	07	3.64
8	08	3.66
9	09	3.68
10	0A	3.70
11	0B	3.72
12	0C	3.74
13	0D	3.76
14	0E	3.78
15	0F	3.80
16	10	3.82
17	11	3.84
18	12	3.86
19	13	3.88
20	14	3.90
21	15	3.92
22	16	3.94
23	17	3.96
24	18	3.98
25	19	4.00
26	1A	4.02
27	1B	4.04
28	1C	4.06
29	1D	4.08
30	1E	4.10
31	1F	4.12
32	20	4.14
33	21	4.16
34	22	4.18
35	23	4.20
36	24	4.22
37	25	4.24
38	26	4.26
39	27	4.28
40	28	4.30
41	29	4.32
42	2A	4.34
43	2B	4.36
44	2C	4.38
45	2D	4.40
46	2E	4.42
47	2F	4.44
48	30	4.44
49	31	4.44
50	32	4.44
51	33	4.44
52	34	4.44
53	35	4.44
54	36	4.44
55	37	4.44
56	38	4.44
57	39	4.44
58	3A	4.44
59	3B	4.44
60	3C	4.44
61	3D	4.44
62	3E	4.44
63	3F	4.44

Note:

6. All register default settings are noted by **bold typeface**.

Charge Initiation

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below V_{OREG} - V_{RCH}
- A power source is connected (PWRIN POR) and battery voltage is below the weak-battery threshold (V_{LOWV}).
- CE# and HZ_MODE are both cleared, after having been set, and a power source is connected.

Charge Current Limit

The default charge current is limited by the IOLEVEL bit (REG5[5]). When this bit is set (default), charge current is limited to 325 mA (22.1 mV across R_{SENSE}) and the ICHG bits are ignored. Resetting IOLEVEL allows the ICHG bits to control the battery charge current limit.

Any attempt to write a value higher than 10 (0AH) results in a value of 10 (0AH) written to the ICHGV bits *(see Table 24).*

Charge Termination Current Limit

Current charge termination is enabled when TE (REG1[3]) = 1. The current level is control by the ITERM bits (REG4[2:0].

PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulate the output voltage and battery charge currents. A cycle-by-cycle current limit of nominally 2.3 A, sensed through Q1, is used to terminate t_{ON}. The synchronous rectifier, Q2, also has a current limit that turns off Q2 at 160mA to prevent current flow from the battery.

When the charge current drops below ~20 mA; the IC runs in Asynchronous Mode, which prevents reverse current from pumping up the input source.

Safety Timer *(see Figure 52)*

At the beginning of the charging process, the IC starts the 15-minute timer (t_{15MIN}). When this timer expires, charging is terminated and the CE# bit is set. Writing to any register through I^2C stops the t_{15MIN} timer, which, in turn, starts a 32-second timer (t_{32SEC}). Setting the TMR_RST bit (REG0[1]) resets the t_{32SEC} timer. If the t_{32SEC} timer times out, all registers (except SAFETY) are set to their default values, a Timer Fault (110) is reported in the fault register, and charging resumes using the default values with the t_{15MIN} timer running.

Since there is only one t_{32SEC} timer on the IC, writing to either TMR_RST bit in either CONTROL0_U or CONTROL0_V resets the timer. The t_{32SEC} timer starts with an I^2C WRITE to either slave address. Timer faults are reported in both U and V registers. A t_{32SEC} fault resets U and V registers 1 – 5.

Normally, charging is controlled by the host with the t_{32SEC} timer running to ensure that the host is active. Charging with the t_{15MIN} timer running is used for charging that is unattended by the host, which would occur when V_{BAT} is insufficient to power the host processor. If the 15-minute timer expires, the IC turns off the charger and indicates a timer fault (110) on the FAULT bits (REG0[2:0]). This prevents overcharge if the host fails to reset the t_{32SEC} timer. The CE# bit is set in the registers where the power sources are connected. For example, if VIN and VBUS are both connected when the t_{15MIN} timer expires, CE#_V and CE_U are both set.

Reset Bit

Setting the RESET bit (Reg4[7]) resets all registers for the slave address used to set the RESET bit. When the RESET bit is set, the t_{32SEC} timer is reset and stopped, charging stops and the IC goes to Charge Configuration Mode *(see Figure 50).* If V_{BAT} < V_{OREG}, charging begins in 15-Minute Mode 262 ms after the RESET bit is set.

PWRIN Validation, Notification, and Non-Compliant Power Source Rejection

Whenever either VBUS_CON or VIN_CON bits have been set, the STAT pin pulses to notify the host processor of a change in status on the input power supply.

Before attempting to charge, the IC attempts to validate its input source by loading the appropriate source with 110 Ω to ensure that the source stays between 4.4 V and VIN_{OVP} for 32 ms. If the input source fails validation, STAT enunciates a fault and the fault bits are set according to the condition of the input source (OVP or poor input source). The PWRIN validation sequence always occurs before charging is initiated or re-initiated (for example, after a PWRIN OVP fault, a V_{RCH} recharge initiation, or resetting the HZ bit). The 32 ms validation time ensures that unfiltered 50/60 Hz chargers and other non-compliant chargers are rejected.

2.5 V Regulator Operation

When the VIN_CON bit is set, indicating that the VIN power source has been plugged in, the V2V5 regulator is enabled.

USB-Friendly Boot Sequence *(see Figure 48)*

At PWRIN POR, when the battery voltage is above the weak-battery threshold (V_{LOW}), the IC goes into Charge Configuration Mode unless the t_{32SEC} timer is enabled by an I^2C write. In that case, the IC begins to charge with the existing register settings.

If V_{BAT} < V_{LOW}, the IC goes into Charge Configuration Mode if the t_{32SEC} timer is not enabled. If V_{BAT} < V_{OREG}, the registers reset and charging begins in 15-Minute Mode. During 15-Minute Mode, the charger uses an input current limit controlled by the OTG pin when charging from VBUS (100mA if OTG is LOW and 500mA if OTG is HIGH).

Even if charging from VIN, the charging current is limited to 325 mA (22.14 mV across 68mΩ) after the registers are reset. This feature can revive a cell whose voltage is too low for reliable host operation until the battery has sufficient charge for the host to boot up and set charge parameters. Charging continues in the absence of host communication even after the battery has reached V_{OREG}, with a default value of 3.54 V, and the charger remains active until t_{15MIN} times out.

Once the host processor begins writing to the IC, charging parameters are set by the host, which must continually reset the t_{32SEC} timer to continue charging using programmed charging parameters. If t_{32SEC}.times out, the register defaults are loaded, the FAULT bits are set to 110, STAT is pulsed, and charging continues with default charge parameters.

At PWRIN POR, if V_{BAT} < V_{LOW} and HZ or CE# were set previously, the IC goes into HZ state, which causes the registers to reset, clearing the HZ and CE# bits when t_{32SEC} expires and beginning t_{15MIN} charging unless the host processor sets the TMR_RST bit.

VBUS Current Limiting

To minimize charging time without overloading VBUS's current limitations, the IC's VBUS current limit can be programmed with the IBUSLIM bits (REG1[7:6]).

The OTG pin establishes the VBUS current limit during 15-Minute Mode charging.

Operational Flow Charts

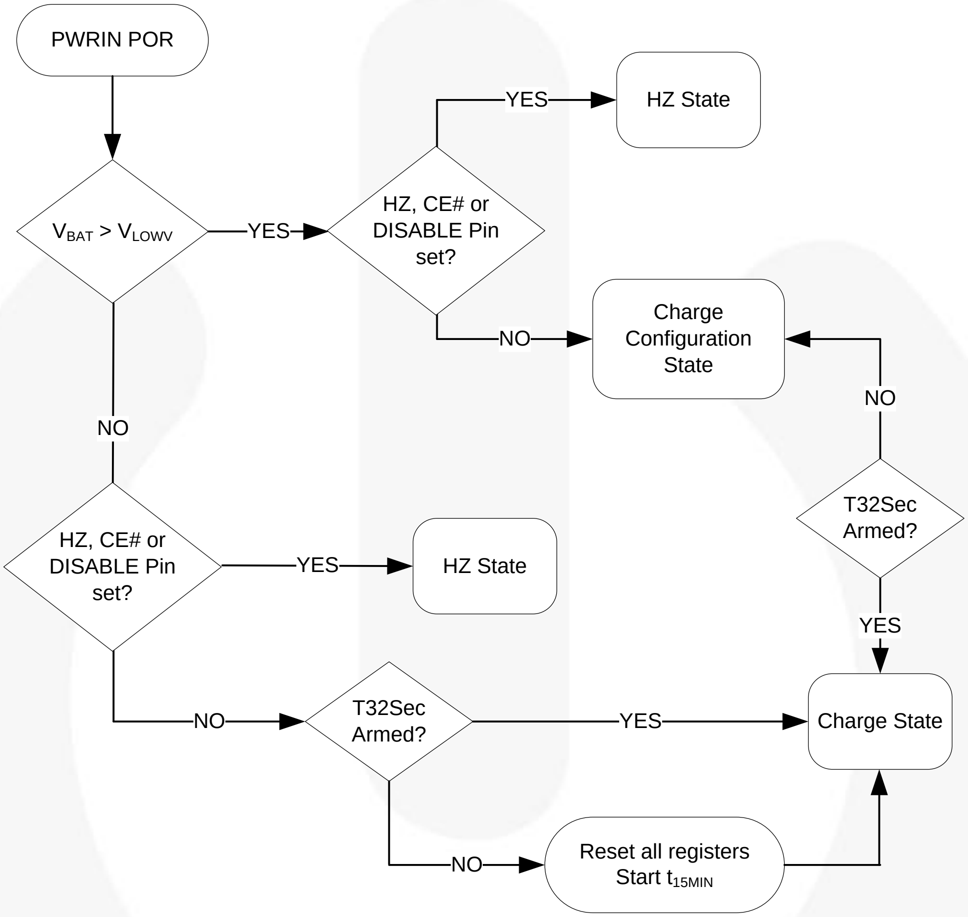


Figure 48. Charger PWRIN POR Flow Chart

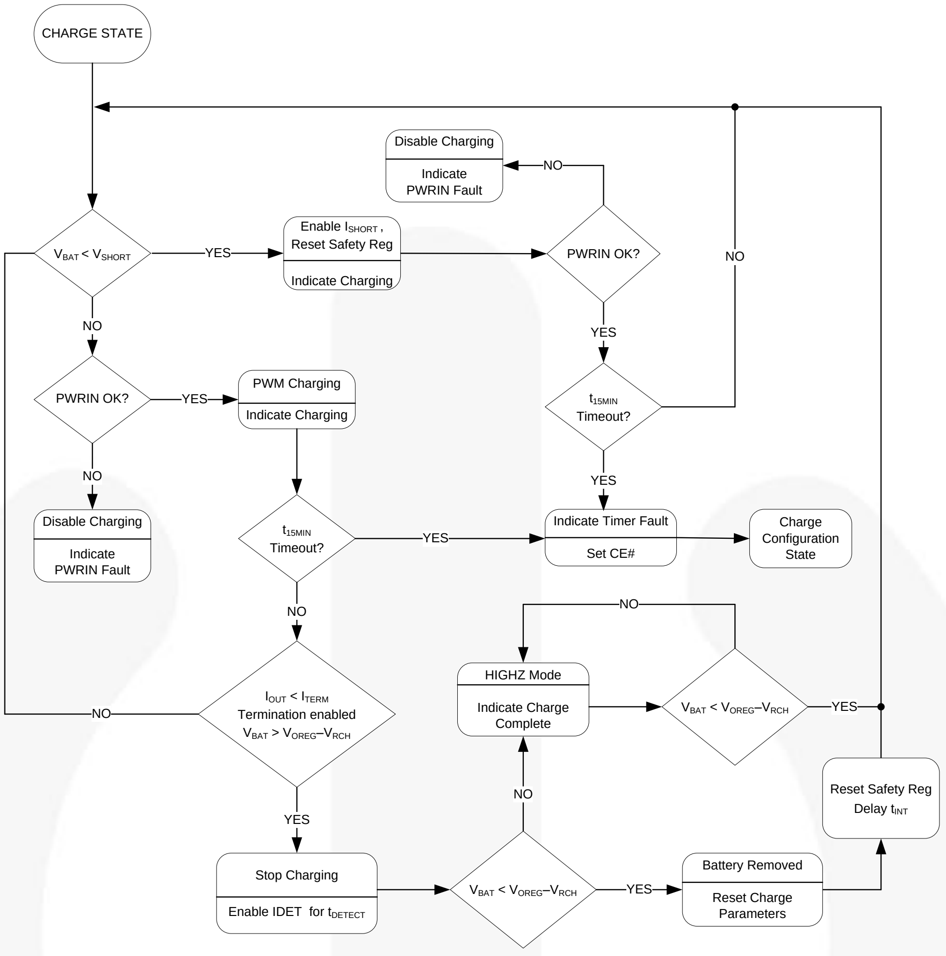


Figure 49. Charge Mode Flow Chart

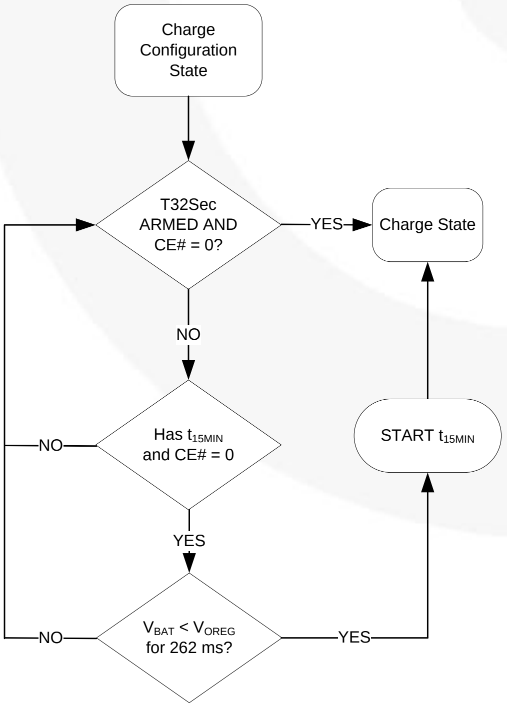


Figure 50. Charge Configuration Flow Chart

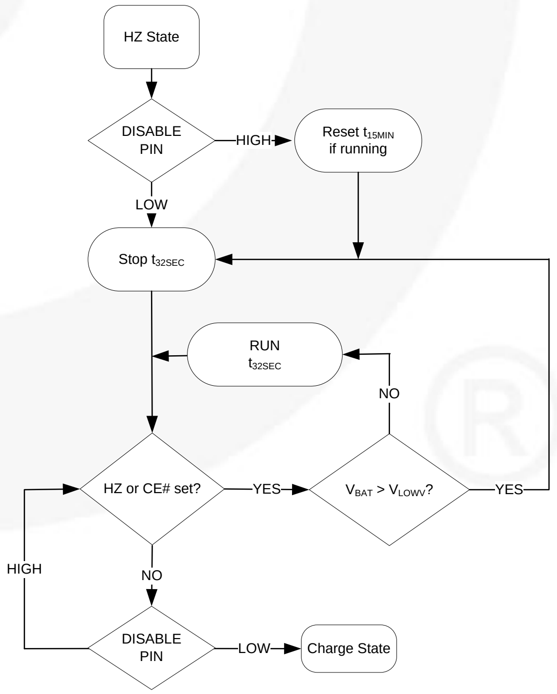


Figure 51. HZ-State Flow Chart

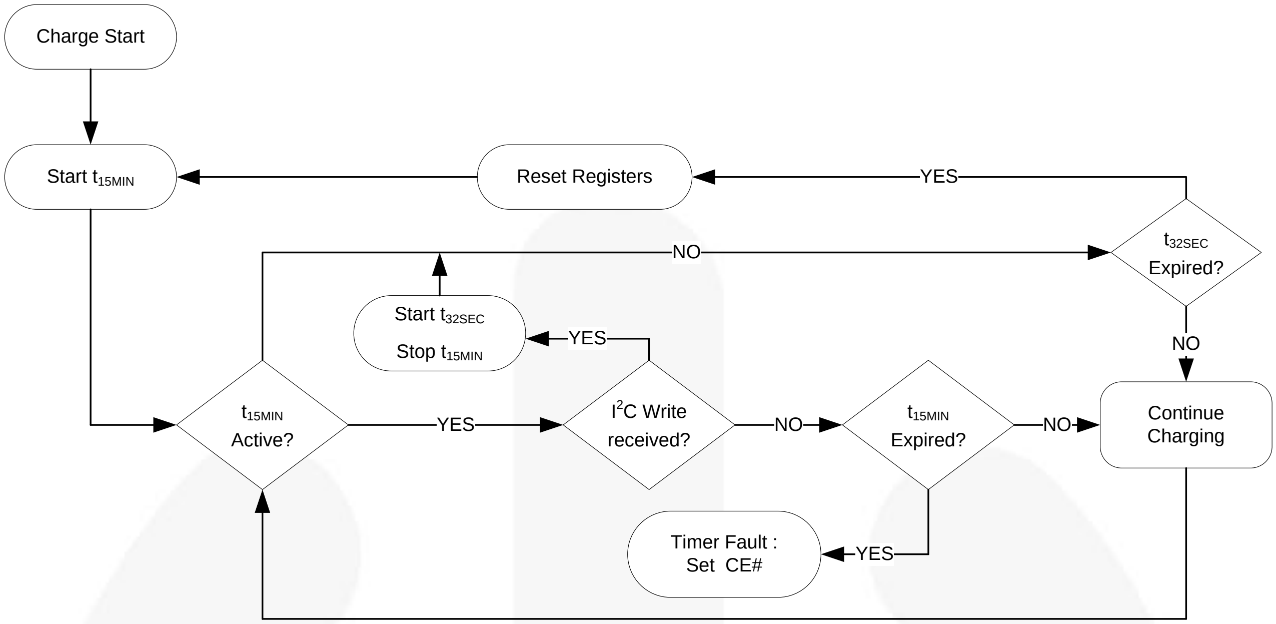


Figure 52. Timer Flow Chart

Special Charger

The IC limits input current in case a current-limited charger is supplying V_{BUS} or V_{IN}. The IC slowly increases the charging current until either:

- I_{BUSLIM} or I_{CHARGE} is reached; or
- $V_{PWRIN} = V_{SP}$ where V_{PWRIN} is the selected input power source *(see Table 4)*.

If V_{PWRIN} collapses to V_{SP} when current is ramping up, the IC charges with an input current that keeps $V_{PWRIN} = V_{SP}$. When the V_{SP} control loop is limiting the charge current, the SP bit (REG5[4]) is set. V_{SP} default value is 4.53 V, but it can be programmed by REG5[2:0].

Safety Settings

A SAFETY register (REG6) prevents the values in OREG (REG2[7:2]) and ICHG (REG4[6:3]) from exceeding the values of the VSAFE and ISAFE values.

After V_{BAT} rises above V_{SHORT}, the SAFETY register is loaded with its default value and may be written only before any other register is written. After writing to any other register, the SAFETY register is locked until V_{BAT} falls below V_{SHORT}. The SAFETY register is reset whenever the SRST pin is LOW.

ISAFE and VSAFE establish values that limit the maximum values of ICHG and OREG used by the control logic. If the host attempts to write a value higher than VSAFE or ISAFE to OREG or ICHG, respectively; the VSAFE, ISAFE value appears as the OREG, ICHG register value, respectively.

For the SAFETY_U register, any attempt to write an ISAFE value higher than 10 (0AH) results in a value of 10 being written to the ISAFE bits. *See Table 21 for VSAFE values and Table 20 and Table 26 for ISAFE values.*

Thermal Regulation and Protection

When the IC's junction temperature reaches T_{CF} (about 120°C) the charger reduces its output current to prevent overheating. If the temperature continues to increase, the current is reduced to 0 when the junction is 10°C above T_{CF}. If the temperature increases beyond $T_{SHUTDOWN}$, charging is suspended, the FAULT bits are set to 101, and SAT is pulsed. In Suspend Mode, all timers stop and the state of the IC's logic is preserved. Charging resumes after the die cools to about 10°C below $T_{SHUTDOWN}$.

Charge Mode Input Supply Protection

Sleep Mode

When V_{BUS} and V_{IN} are both below V_{BAT}, the IC enters Sleep Mode. To prevent the battery from discharging into VBUS, reverse current is prevented by body switching Q1 when PMID1 falls below V_{BAT}.

Similarly, when V_{IN} falls below V_{BAT}, Q4 turns off, blocking battery current flow into VIN.

Input Supply Low-Voltage Detection

The IC continuously monitors V_{PWRIN} during charging. If the input voltage for the active charging source falls below 3.7 V, the IC terminates charging, pulses the STAT pin, sets STAT bits to 11, and sets the FAULT bits to 011 for the appropriate input source.

If the power source recovers above the $V_{IN(MIN)}$ rising threshold after timer t_{INT} (about two seconds), the charging process is repeated. This prevents the USB power bus from collapsing or oscillating when the IC is connected to a suspended USB port or an OTG device with low current capability.

Input Over-Voltage Detection

When V_{BUS} exceeds its OVP threshold, the IC:

1. Turns off Q3;
2. Suspends charging from V_{BUS}; and
3. Sets the FAULTU bits to 001, STATU bits to 11, and pulses the STAT pin.

When V_{BUS} falls to about 150 mV below $VBUS_{OVP}$, the fault is cleared, and charging resumes after V_{BUS} is revalidated.

If V_{IN} exceeds its OVP threshold, the IC:

1. Turns off Q4;
2. Suspends charging from V_{IN}; and
3. Sets the FAULTV bits to 001, STATV bits to 11, and pulses the STAT pin.

Charge Mode Battery Detection & Protection

V_{BAT} Over-Voltage Protection

The OREG voltage regulation loop prevents V_{BAT} from overshooting the OREG voltage by more than 50 mV when the battery is removed. When the PWM charger is running with no battery, the TE bit is not set, and a battery is inserted that's charged to a voltage higher than V_{OREG}; PWM pulses stop. If no further pulses occur for 30 ms, the IC sets the FAULT bits to 100, STAT bits to 11, and pulses the STAT pin.

Battery Detection During Charging

The IC can detect presence, absence, or removal of a battery. During normal charging, once V_{BAT} is greater than $V_{OREG} - V_{RCH}$ and the termination charge current is detected; the IC terminates charging and sets the STAT bits to 10. It then turns on a discharge current, I_{DETECT}, for t_{DETECT} . If V_{BAT} is still above $V_{OREG} - V_{RCH}$, the battery is present and the IC sets the FAULT bits to 000. If V_{BAT} is below $V_{OREG} - V_{RCH}$, the battery is absent and the IC:

1. Sets the registers to their default values;
2. Sets the FAULT bits to 111; and
3. Resumes charging with default values after delay t_{INT}.

Battery Detection During Power-up

At PWRIN POR, if the charger is in 15-Minute Mode (no I^2C writes from the host detected), the IC starts a 32 ms timer when V_{BAT} crosses V_{SHORT} and starts PWM charging. If V_{BAT} exceeds 3.7 V within a 32 ms period, the IC determines that the battery is not present and:

1. Enters Charge Configuration Mode;
2. Sets the FAULT bits to 111 (no battery) and resets the SAFETY registers; and
3. Disables auto-charging until the next PWRIN POR.

Battery Short-Circuit Protection

If the battery voltage is below the short-circuit threshold (V_{SHORT}); a linear current source, I_{SHORT}, supplies VBAT until $V_{BAT} > V_{SHORT}$.

Charger Status / Fault Status

The STAT pin indicates the operating condition of the IC and provides a fault indicator for interrupt-driven systems. When a fault condition occurs, the STAT pin pulses LOW for 125 µs. If a new fault replaces the prior fault, STAT issues a new pulse.

The FAULT bits (R0[2:0]) indicate the type of fault in Charge Mode *(see Table 14)*. FAULT bits return to 000 once R0 is read if the fault condition has cleared.

Charge Mode Control Bits

When set, the HZ_VBUS and HZ_VIN bits prevent charging from the VBUS or VIN input sources, respectively. The DIS pin prevents all charging when set, regardless of the state of the HZ bits.

Table 6. DIS Pin and HZ Bit Functionality

Charging	DIS PIN	HZ
ENABLE	0	0
DISABLE	X	1
DISABLE	1	X

Boost Mode

Boost Mode can be enabled when the IC is in 32-Second Mode (host sets TMR_RST before the t_{32SEC} expired) with the OTG pin and OPA_MODE bits as indicated in Table 7. The OTG ACTIVE state is 1 if OTG_PL =1, and 0 when OTG_PL =0.

If boost is active using the OTG pin, boost mode is initiated even if the HZ_VBUS = 1. The HZ_VBUS bit overrides the OPA_MODE bit.

Table 7. Enabling Boost

OTG_EN	OTG PIN	HZ_VBUS	OPA_MODE	BOOST
1	ACTIVE	X	X	Enabled
1	X	0	1	Enabled
1	$\overline{\text{ACTIVE}}$	0	0	Disabled
1	$\overline{\text{ACTIVE}}$	X	0	Disabled
0	X	1	X	Disabled

To remain in Boost Mode, the TMR_RST bit must be set by the host before the t_{32SEC} timer expires. If t_{32SEC} times out in Boost Mode; the IC reverts to High-Impedance Mode, pulses the STAT pin, sets the FAULT bits to 110, and resets the BOOST bit. POR or USB activity clears the fault condition.

The IC can operate its boost regulator while simultaneously charging from VIN. If the IC is charging from VIN when the boost regulator is enabled, charging pauses until the boost soft-start has completed.

Boost PWM Control

The IC uses a minimum on-time, and computed minimum off-time, to regulate V_{BUS}. The computed off-time is designed to keep the switching frequency constant near 3 MHz when the regulator's inductor current is continuous (CCM).

The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During CCM Mode, the output voltage drops slightly as the input current rises. With a constant V_{BAT}, this appears as a constant output resistance.

The "droop" caused by the output resistance when a load is applied allows the regulator to respond smoothly to load transients with no undershoot from the load line. This can be seen in Figure 34.

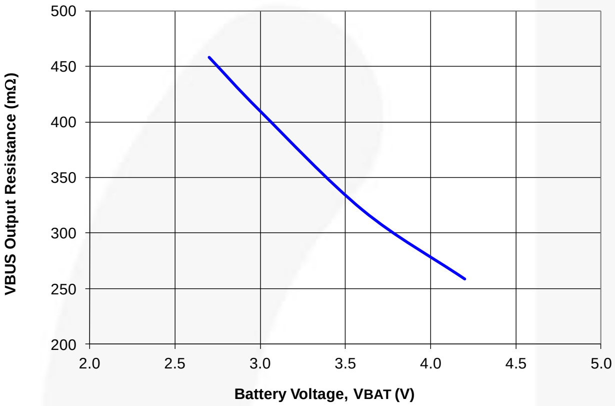


Figure 53. Output Resistance (R_{OUT})

V_{BUS} as a function of I_{LOAD} can be computed when the regulator is in PWM Mode (continuous conduction) as:

$$V_{BUS} = 5.05 - R_{OUT} \bullet I_{LOAD} \qquad \text{EQ. 1}$$

At 3.6 V_{BAT} and I_{LOAD} = 300 mA, V_{BUS} would droop to about:

$$V_{BUS} = 5.05 - 0.32 \bullet 0.3 = 4.95V \qquad \text{EQ. 2}$$

At 2.7 V_{BAT}, with I_{LOAD} = 200 mA, V_{BUS} would droop to about:

$$V_{BUS} = 5.05 - 0.45 \bullet 0.2 - 4.96V \qquad \text{EQ. 3}$$

Pulse Frequency Modulated (PFM) Mode

If $V_{BUS} > VREF_{BOOST}$ (nominally 5.05 V) when the minimum off time has ended, the regulator enters PFM Mode. Boost pulses are inhibited until $V_{BUS} < VREF_{BOOST}$. The minimum on-time is increased to enable the output to pump up sufficiently with each PFM boost pulse. The regulator behaves like a constant on-time regulator, with the bottom of its output voltage ripple at 5.05 V in PFM Mode. Since PFM voltage ripple is typically 20 mV_{P-P}, $VBUS_{(PFM)}$ is nominally 5.06 V.

Table 8. Boost PWM Operating States

State	Description	Invoked When:
SCHK	Short-Circuit Check	$V_{BAT} > V_{BUS}$ and $V_{BUS} < 1V$
LIN1	Linear Startup	$V_{BAT} > 1V$
SS	Boost Soft-Start	$V_{BUS} < V_{BST}$
BST	Boost Operating Mode	$V_{BAT} > V_{UVLO}$ and SS completed

Shutdown State

When the boost regulator is shut down, Q3 is off, preventing current flow from VBAT to VBUS. Q1 is also off, which prevents current flow from VBUS to VBAT.

SCHK State

The SCHK state turns on a switch with an on-resistance of about 120 Ω from VBAT to VBUS and waits for V_{BUS} to rise to about 1 V before proceeding with boost soft-start. This prevents high current drain from the battery, which could occur if Q3 is turned on into a short circuit. If V_{BUS} fails to rise above 1 V within 8 ms, a boost overload fault is enunciated.

LIN1 State

A portion of Q3 is turned on (on-resistance = 1 Ω) to charge V_{BUS} from 1V to V_{PMID1}. V_{PMID1} is about 0.7 V below V_{BAT}. This state ends when $V_{PMID1} - V_{BUS} < 0.4$ V. If V_{BUS} fails to achieve $V_{PMID1} - 0.4$ V within 512 µs, a boost overload fault is enunciated.

SS State

When $V_{BUS} > V_{PMID1} - 0.4$ V, the boost regulator begins switching. The output slews up until V_{BUS} is within 10% of its setpoint; at which time, the regulation loop is closed and the boost reference is digitally stepped to 5.07 V.

If the output fails to achieve 90% of its setpoint (V_{BST}) within 512 µs, a boost overload fault is enunciated.

BST State

This is the normal operating mode of the regulator.

Thermal

If the die temperature reaches 120°C while the boost and charger are both operating, charging stops for at least 10 ms, then resumes when the die temperature falls below 120°C.

Boost Fault States

A BOOST fault is enunciated by the STAT pin pulsing and FAULT status bits under any of the following conditions.

Table 9. Fault Status Bits during Boost Mode

Fault Bit			Fault Description
B2	**B1**	**B0**	
0	0	0	Normal (no fault)
0	0	1	V_{BUS} > $VBUS_{OVP}$
0	1	0	V_{BUS} fails to achieve the voltage required to advance to the next state during soft-start or sustained (>32 ms) current limit during the BST state.
0	1	1	V_{BAT} < $UVLO_{BST}$
1	0	0	N/A: This code will not appear
1	0	1	Thermal shutdown
1	1	0	Timer fault
1	1	1	N/A: This code will not appear

Once a fault is triggered, the OPA_MODE bit is reset.

If the boost was started by setting the OTG pin and OTG_EN bits, the boost attempts to restart after a fault following a “cool-off” time of 128 ms.

VREF

The VREF pin provides bias current to the charging circuit while VIN is the power source. This pin follows PMID2, but its voltage is limited to 5.8 V. Up to 5 mA of current can be drawn from the VREF pin to power external devices.

LED Control

An LED driver provides a constant current to drive the anode of a charge indicator LED. The LED flashes during charging. The LED_CONTROL register provides control of the LED driver and can be programmed to flash the LED when charging is disabled.

LED_CONTROL is reset whenever the IC begins charging in 15-Minute Mode. This occurs after VBUS or VIN POR with a weak battery when t_{32SEC} is not running or when t_{32SEC} expires.

Recommended PCB Layout

To limit the high-voltage excursions and stresses on the chargers’ internal switching MOSFETs, it is critical to limit the total loop length from PMID back to the GND return, including the length of the CMID bypass capacitors. The layout below achieves this goal.

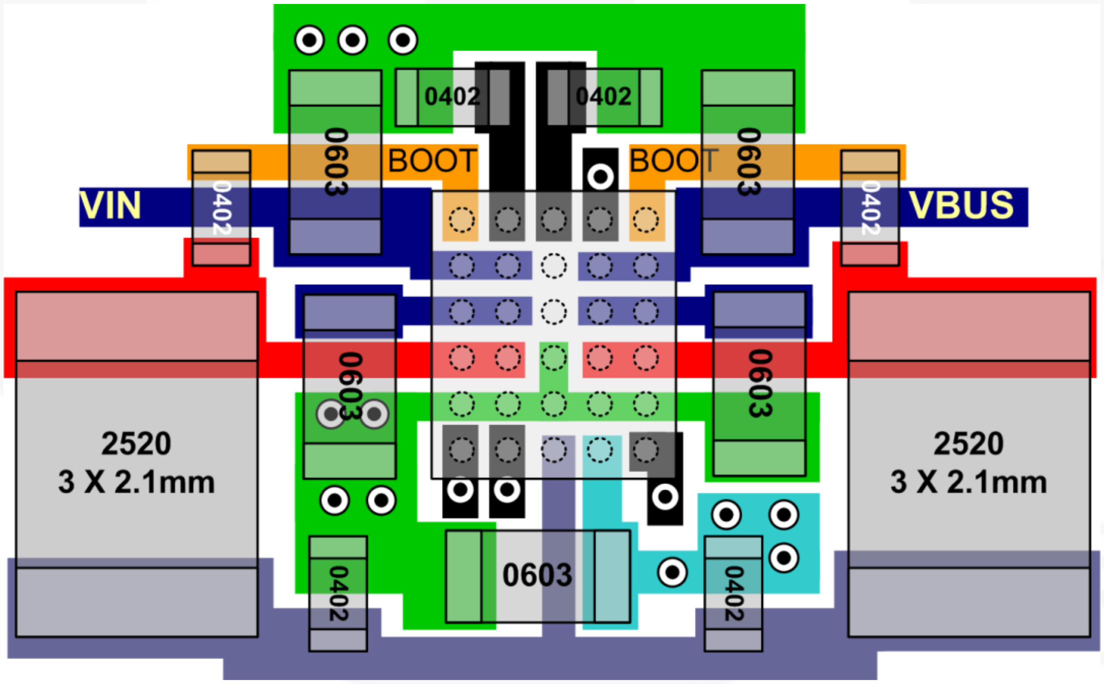


Figure 54. Recommended Layout for High-Current Charging, Using 2520 Inductors

I^{2}C Interface

The serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Modes per the I^{2}C-Bus® specifications. The SCL line is an input and its SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and when signaling ACK. All data is shifted in MSB (bit 7) first.

Bus Timing

As shown in Figure 55, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

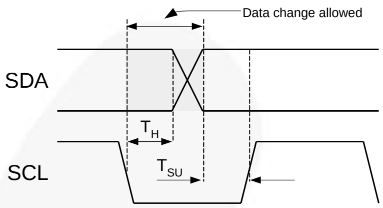


Figure 55. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCL HIGH. A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH, as shown in Figure 56.

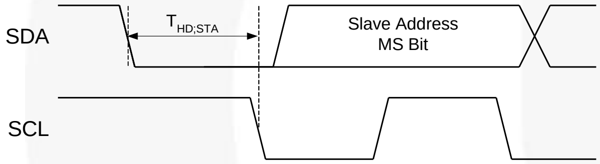


Figure 56. Start Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 57.

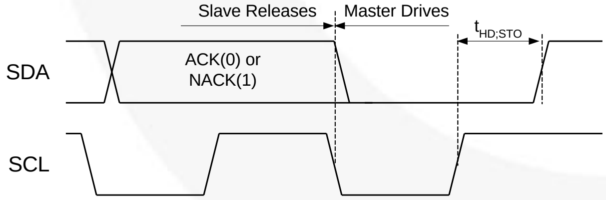


Figure 57. Stop Bit

During a read from the FAN54300 *(see Figure 60)*, the master issues a "REPEATED START" after sending the register address and before resending the slave address. The REPEATED START is a 1-to-0 transition on SDA while SCL is HIGH, as shown in Figure 58.

High-Speed (HS) Mode

The protocols for High-Speed (HS), Low-Speed (LS), and Fast-Speed (FS) Modes are identical, except the bus speed for HS Mode is 3.4 MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a START condition. The master code is sent in Fast or Fast-Plus Mode (less than 1 MHz clock). Slaves do not ACK this transmission.

The master then generates a REPEATED START condition *(see Figure 58)* that causes all slaves on the bus to switch to HS Mode. The master then sends I^{2}C packets, as described above, using the HS Mode clock rate and timing.

The bus remains in HS Mode until a stop bit (Figure 57) is sent by the master. While in HS Mode, packets are separated by REPEATED START conditions (Figure 58).

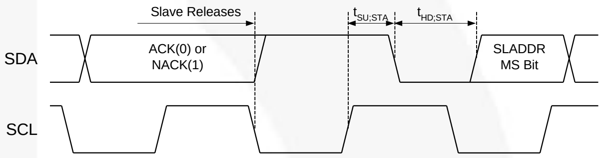


Figure 58. Repeated Start Timing

Read and Write Transactions

The following figures outline the sequences for data read and write. Bus control is signified by the shading of the packet, defined as ▨ Master Drives Bus and ☐ Slave Drives Bus. All addresses and data are MSB first.

Table 10. Bit Definitions for Figure 59 and Figure 60

Symbol	Definition
S	START, *see Figure 56.*
A	ACK. The slave drives SDA to 0 to acknowledge the preceding packet.
$\overline{A}$	NACK. The slave sends a 1 to NACK the preceding packet.
R	Repeated START, *see Figure 58*
P	STOP, *see Figure 57.*

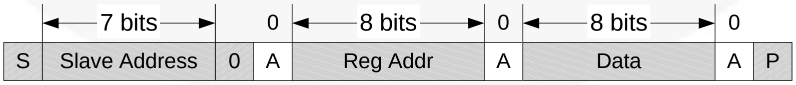


Figure 59. Write Transaction

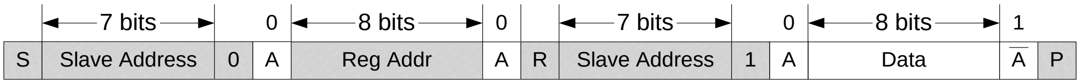


Figure 60. Read Transaction

Register Descriptions

Table 11. I²C Slave Address

Hex	7	6	5	4	3	2	1	0	
D4	1	1	0	1	0	1	0	R/$\overline{W}$	**VIN Charger**
D6	1	1	0	1	0	1	1	R/$\overline{W}$	**USB Charger**

Table 12. I²C Register Address

Name	Register Address	Slave Address	Affects	7	6	5	4	3	2	1	0
CONTROL0_U	0	D6	USB	0	0	0	0	0	0	0	0
CONTROL1_U	1	D6	USB	0	0	0	0	0	0	0	1
OREG_U	2	D6	USB	0	0	0	0	0	0	1	0
IC_INFO_U	3	D6	Both	0	0	0	0	0	0	1	1
IBAT_U	4	D6	USB	0	0	0	0	0	1	0	0
SP_CHARGER_U	5	D6	USB	0	0	0	0	0	1	0	1
SAFE_U	6	D6	USB	0	0	0	0	0	1	1	0
CONTROL0_V	0	D4	VIN	0	0	0	0	0	0	0	0
CONTROL1_V	1	D4	VIN	0	0	0	0	0	0	0	1
OREG_V	2	D4	VIN	0	0	0	0	0	0	1	0
IC_INFO_V	3	D4	Both	0	0	0	0	0	0	1	1
IBAT_V	4	D4	VIN	0	0	0	0	0	1	0	0
SP_CHARGER_V	5	D4	VIN	0	0	0	0	0	1	0	1
SAFE_V	6	D4	VIN	0	0	0	0	0	1	1	0
LED_CONTROL	7	D4/D6	Both	0	0	0	0	0	1	1	1
CHARGE_STATUS	8	D4/D6	Both	0	0	0	0	1	0	0	0
INPUT_STATUS	9	D4/D6	Both	0	0	0	0	1	0	0	1
DIE_REV	14	D4/D6	Both	0	0	0	1	0	1	0	0

Register Bit Definitions

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td colspan="4">CONTROL0_U Reg Addr: 0 Slave Addr: D6 Default = x1xx xxxx</td></tr>
<tr><td rowspan="2">7</td><td>TMR_RST</td><td>W</td><td>Writing a 1 resets the t_{32SEC} timer. Writing a 0 has no effect.</td></tr>
<tr><td>OTG</td><td>R</td><td>Returns the OTG pin level (1 = OTG pin HIGH)</td></tr>
<tr><td>6</td><td>EN_STU</td><td>R/W</td><td>0: STAT pin does not go LOW when charging from USB source.
1: STAT pin function is enabled.</td></tr>
<tr><td>5:4</td><td>STAT_U</td><td>R</td><td>USB charger status
Table 13. USB Charger Status Bits
<table>
<tr><td>00</td><td>Normal (no fault) / Ready</td></tr>
<tr><td>01</td><td>Charge in progress from USB source</td></tr>
<tr><td>10</td><td>Charge done</td></tr>
<tr><td>11</td><td>USB charger fault</td></tr>
</table></td></tr>
<tr><td>3</td><td>BOOST</td><td>R</td><td>0: OTG boost is not active.
1: OTG boost is active.</td></tr>
<tr><td>2:0</td><td>FAULT_U</td><td>R</td><td>Delineates USB Charger and OTG Boost Faults
Table 14. USB Fault Bits
<table>
<tr><th colspan="3">Bits</th><th rowspan="2">Charger Mode</th><th rowspan="2">Boost Mode</th></tr>
<tr><th>2</th><th>1</th><th>0</th></tr>
<tr><td>0</td><td>0</td><td>0</td><td>Normal (no fault)</td><td>Normal (no fault)</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>$V_{BUS} > VBUS_{OVP}$</td><td>$V_{BUS} > VBUS_{OVP}$</td></tr>
<tr><td>0</td><td>1</td><td>0</td><td>Sleep Mode: $V_{BUS} < V_{BAT}$</td><td>Boost overload</td></tr>
<tr><td>0</td><td>1</td><td>1</td><td>Poor USB input source</td><td>$V_{BAT} < UVLO_{BST}$</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>Battery OVP</td><td>N/A: This code will not appear</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>Thermal shutdown</td><td>Thermal shutdown</td></tr>
<tr><td>1</td><td>1</td><td>0</td><td>Timer fault</td><td>Timer fault</td></tr>
<tr><td>1</td><td>1</td><td>1</td><td>No battery</td><td>N/A: This code will not appear</td></tr>
</table></td></tr>
</table>

Note:

7. Default values are in **bold** text.

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td colspan="4">CONTROL1_U Reg Addr: 1 Slave Addr: D6 Default = 0011 0000</td></tr>
<tr><td>7:6</td><td>IBUSLIM</td><td>R/W</td><td>USB bus current limit
Table 15. IBUSLIM: USB bus current limit
<table>
<tr><th>[7:6]</th><th>IBUS Current Limit</th></tr>
<tr><td>00</td><td>100 mA</td></tr>
<tr><td>01</td><td>500 mA</td></tr>
<tr><td>10</td><td>800 mA</td></tr>
<tr><td>11</td><td>No limit</td></tr>
</table></td></tr>
<tr><td>5:4</td><td>VLOWV_U</td><td>R/W</td><td>Weak Battery Threshold. This register determines V_{LOWV} threshold when V_{BUS} is charging.
Table 16. V_{LOWV}: Weak Battery Threshold
<table>
<tr><th>[5:4]</th><th>IBUS Current Limit</th></tr>
<tr><td>00</td><td>3.4 V</td></tr>
<tr><td>01</td><td>3.5 V</td></tr>
<tr><td>10</td><td>3.6 V</td></tr>
<tr><td>11</td><td>3.7 V</td></tr>
</table></td></tr>
<tr><td>3</td><td>TE_U</td><td>R/W</td><td>0: Charge termination is disabled when charging from USB.
1: Charge termination is enabled for USB charging.</td></tr>
<tr><td>2</td><td>CE#_U</td><td>R/W</td><td>0: USB charger is enabled.
1: USB charger is disabled. This bit is set when t_{15MIN} expires, regardless of which input source is charging.</td></tr>
<tr><td>1</td><td>HZ_U</td><td>R/W</td><td>0: USB charger is not in High-Impedance Mode.
1: USB charger is in High-Impedance Mode.</td></tr>
<tr><td>0</td><td>OPA_ MODE</td><td>R/W</td><td>0: Boost Mode disabled unless enabled with the OTG pin and OTG_EN HIGH.
1: Boost Mode enabled unless HZ_U is set.</td></tr>
<tr><td colspan="4">OREG_U Reg Addr: 2 Slave Addr: D6 Default = 0000 1010</td></tr>
<tr><td>7:2</td><td>OREGU</td><td>R/W</td><td>Charger output “float” voltage when charging from USB source.
Programmable from 3.5 to 4.44 V in 20 mV increments. Defaults to 000010 (3.54 V) <i>(see Table 5).</i></td></tr>
<tr><td>1</td><td>OTG_PL</td><td>R/W</td><td>0: OTG pin is active LOW.
1: OTG pin is active HIGH.</td></tr>
<tr><td>0</td><td>OTG_EN</td><td>R/W</td><td>0: OTG pin does not enable boost when HIGH.
1: OTG pin enables boost when HIGH.</td></tr>
<tr><td colspan="4">IC_INFO_U Reg Addr: 3 Slave Addr: D4 or D6 Default = 100x x000</td></tr>
<tr><td>7:5</td><td>VENDOR</td><td>R</td><td>100: Identifies Fairchild as the supplier.</td></tr>
<tr><td>4:3</td><td>PN_U</td><td>R</td><td>Part number bits. FAN54300 = 10</td></tr>
<tr><td>2:0</td><td>REV</td><td>R</td><td>IC Revision. Revision is 1.X where X is the decimal of these 3 bits.</td></tr>
<tr><td colspan="4">DIE_REV Reg Addr: 14H Slave Addr: D4 or D6 Default = 0000 XXXX</td></tr>
<tr><td>7:4</td><td>Reserved</td><td>R</td><td>These bits return 0.</td></tr>
<tr><td>3:0</td><td>REV_D</td><td>R</td><td>Die revision. These bits uniquely identify the full revision of the IC. REV bits change whenever there is a significant design change. REV_D bits change whenever any masks are revised.</td></tr>
</table>

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td colspan="4">**IBAT_U** **Reg Addr: 4** **Slave Addr: D6 Default = 0000 1001**</td></tr>
<tr><td>7</td><td>RESETU</td><td>W</td><td>Writing a 1 resets all registers programmed with slave address D4, except the Safety register (Reg6), to their defaults. Writing a 0 has no effect. Read returns 0.</td></tr>
<tr><td>6:4</td><td>ICHGU</td><td>R/W</td><td>Sets the maximum charge current (I_{CHARGE}) when charging from VBUS when IO_LEVELU = 0.

Table 17. I_{CHARGE} as a Function of the ICHGU Bits and R_{SENSE} Resistor Value
<table>
<tr><th rowspan="2">BIN</th><th rowspan="2">HEX</th><th rowspan="2">V_{RSENSE} (mV)</th><th colspan="2">$I_{OCHARGE}$ (mA)</th><th></th></tr>
<tr><th>68mΩ</th><th>100mΩ</th><th>IOREF</th></tr>
<tr><td>**000**</td><td>**00**</td><td>**37.4**</td><td>**550**</td><td>**374**</td><td>704</td></tr>
<tr><td>001</td><td>01</td><td>44.2</td><td>650</td><td>442</td><td>832</td></tr>
<tr><td>010</td><td>02</td><td>51.0</td><td>750</td><td>510</td><td>960</td></tr>
<tr><td>011</td><td>03</td><td>57.8</td><td>850</td><td>578</td><td>1088</td></tr>
<tr><td>100</td><td>04</td><td>64.6</td><td>950</td><td>646</td><td>1216</td></tr>
<tr><td>101</td><td>05</td><td>71.4</td><td>1,050</td><td>714</td><td>1344</td></tr>
<tr><td>110</td><td>06</td><td>78.2</td><td>1,150</td><td>782</td><td>1472</td></tr>
<tr><td>111</td><td>07</td><td>85.0</td><td>1,250</td><td>850</td><td>1600</td></tr>
</table>

Note that when charging from a USB source, charger current is limited to 1250 mA (R_{SENSE} = 68mΩ).</td></tr>
<tr><td>3</td><td>Reserved</td><td>R</td><td>This bit returns 1.</td></tr>
<tr><td>2:0</td><td>ITERMU</td><td>R/W</td><td>Sets the current at which charging terminates when charging from VBUS if the TE bit is set.

Table 18. I_{CHARGE} Termination Current as a Function of ITERM bits and R_{SENSE} Resistor Value
<table>
<tr><th rowspan="2">BIN</th><th rowspan="2">HEX</th><th rowspan="2">V_{RSENSE} (mV)</th><th colspan="2">I_{TERM} (mA)</th></tr>
<tr><th>68mΩ</th><th>100mΩ</th></tr>
<tr><td>000</td><td>00</td><td>3.3</td><td>49</td><td>33</td></tr>
<tr><td>**001**</td><td>**01**</td><td>**6.6**</td><td>**97**</td><td>**66**</td></tr>
<tr><td>010</td><td>02</td><td>9.9</td><td>146</td><td>99</td></tr>
<tr><td>011</td><td>03</td><td>13.2</td><td>194</td><td>132</td></tr>
<tr><td>100</td><td>04</td><td>16.5</td><td>243</td><td>165</td></tr>
<tr><td>101</td><td>05</td><td>19.8</td><td>291</td><td>198</td></tr>
<tr><td>110</td><td>06</td><td>23.1</td><td>340</td><td>231</td></tr>
<tr><td>111</td><td>07</td><td>26.4</td><td>388</td><td>264</td></tr>
</table></td></tr>
</table>

Bit	Name	Type	Description
SP_CHARGER_U		**Reg Addr: 5**	**Slave Addr: D6 Default = 0x1x x100**
7	Reserved	R	This bit returns 0.
6	VBUS_CON	R	Mirror of INPUT_STATUS[5] *(see INPUT_STATUS register description)*
5	IO_LEVEL	R/W	0: Output current is controlled by IOCHARGE bits for charging from VBUS. **When charging from VBUS, the voltage across R_{SENSE} for output current control is set to 22.1 mV (325 mA for R_{SENSE} = 68 mΩ, 221 mA for 100 mΩ).**
4	SPU	R	Special charger loop is not active. Input power source is able to stay above V_{SP}. SPU = 0 when VBUS is not PWM charging. 1: Special charger loop is active and controlling the charging current.
3	VIN_CON	R	Mirror of INPUT_STATUS[7] *(see INPUT_STATUS register description)*

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td>2:0</td><td>VSPU</td><td>R/W</td><td>Sets the special charger control loop reference voltage when charging from V_{BUS}. If V_{BUS} falls below this voltage, battery current is reduced until the input voltage is at or above V_{SP}.

Table 19. V_{SP} Special Charger Reference Voltage

<table>
<tr><th>DEC</th><th>BIN</th><th>V_{SP}</th></tr>
<tr><td>0</td><td>000</td><td>4.21</td></tr>
<tr><td>1</td><td>001</td><td>4.29</td></tr>
<tr><td>2</td><td>010</td><td>4.37</td></tr>
<tr><td>3</td><td>011</td><td>4.45</td></tr>
<tr><td>**4**</td><td>**100**</td><td>4.53</td></tr>
<tr><td>5</td><td>101</td><td>4.61</td></tr>
<tr><td>6</td><td>110</td><td>4.69</td></tr>
<tr><td>7</td><td>111</td><td>4.77</td></tr>
</table>
</td></tr>
<tr><td colspan="3">**SAFE_U**</td><td>**Reg Addr: 6** **Slave Addr: D6 Default = 0100 0000**</td></tr>
<tr><td>7</td><td>Reserved</td><td>R</td><td>This bit returns 0.</td></tr>
<tr><td>6:4</td><td>ISAFEU</td><td>R/W</td><td>Any attempt to write a value to ICHGU higher than the contents of ISAFEU sets ICHGU = ISAFEU.

Table 20. USB Charging I_{CHARGE} Limit as a Function of the ISAFEU Bits

<table>
<tr><th rowspan="2">BIN</th><th rowspan="2">HEX</th><th rowspan="2">V_{RSENSE} (mV)</th><th colspan="2">I_{SAFE} (mA)</th></tr>
<tr><th>68mΩ</th><th>100mΩ</th></tr>
<tr><td>000</td><td>00</td><td>37.4</td><td>550</td><td>374</td></tr>
<tr><td>001</td><td>01</td><td>44.2</td><td>650</td><td>442</td></tr>
<tr><td>010</td><td>02</td><td>51.0</td><td>750</td><td>510</td></tr>
<tr><td>011</td><td>03</td><td>57.8</td><td>850</td><td>578</td></tr>
<tr><td>**100**</td><td>**04**</td><td>**64.6**</td><td>**950**</td><td>**646**</td></tr>
<tr><td>101</td><td>05</td><td>71.4</td><td>1,050</td><td>714</td></tr>
<tr><td>110</td><td>06</td><td>78.2</td><td>1,150</td><td>782</td></tr>
<tr><td>111</td><td>07</td><td>85.0</td><td>1,250</td><td>850</td></tr>
</table>
</td></tr>
<tr><td>3:0</td><td>VSAFEU</td><td>R/W</td><td>Any attempt to write a value to OREGU that is higher than the value in the Max. OREG column (below) results in OREGU = Max OREG.

Table 21. V_{OREG} Limit as a Function of the VSAFEU Bits when Charging from VBUS

<table>
<tr><th>DEC</th><th>BIN</th><th>Max OREG (REG2[7:2])</th><th>VOREG MAX</th></tr>
<tr><td>**0**</td><td>**0000**</td><td>**100011**</td><td>**4.20**</td></tr>
<tr><td>1</td><td>0001</td><td>100100</td><td>4.22</td></tr>
<tr><td>2</td><td>0010</td><td>100101</td><td>4.24</td></tr>
<tr><td>3</td><td>0011</td><td>100110</td><td>4.26</td></tr>
<tr><td>4</td><td>0100</td><td>100111</td><td>4.28</td></tr>
<tr><td>5</td><td>0101</td><td>101000</td><td>4.30</td></tr>
<tr><td>6</td><td>0110</td><td>101001</td><td>4.32</td></tr>
<tr><td>7</td><td>0111</td><td>101010</td><td>4.34</td></tr>
<tr><td>8</td><td>1000</td><td>101011</td><td>4.36</td></tr>
<tr><td>9</td><td>1001</td><td>101100</td><td>4.38</td></tr>
<tr><td>10</td><td>1010</td><td>101101</td><td>4.40</td></tr>
<tr><td>11</td><td>1011</td><td>101110</td><td>4.42</td></tr>
<tr><td>12</td><td>1100</td><td>101111</td><td>4.44</td></tr>
<tr><td>13</td><td>1101</td><td>110000</td><td>4.44</td></tr>
<tr><td>14</td><td>1110</td><td>110001</td><td>4.44</td></tr>
<tr><td>15</td><td>1111</td><td>110010</td><td>4.44</td></tr>
</table>
</td></tr>
</table>

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td colspan="3">CONTROL0_V</td><td>Reg Addr: 0 Slave Addr: D4 Default = x1xx 0xxx</td></tr>
<tr><td></td><td>TMR_RST
SRST</td><td>W
R</td><td>Writing a 1 resets the t_{32SEC} timer. Writing a 0 has no effect.
Returns the SRST pin level (1 = SRST pin HIGH).</td></tr>
<tr><td>6</td><td>EN_STV</td><td>R/W</td><td>0: STAT pin does not go LOW when charging from V_{IN} source.
1: STAT pin function is enabled for V_{IN} source.</td></tr>
<tr><td>5:4</td><td>STAT_V</td><td>R</td><td>Table 22. VIN Charger Status Bits
<table>
<tr><td>00</td><td>Normal (no fault)</td></tr>
<tr><td>01</td><td>Charge in progress from VIN source</td></tr>
<tr><td>10</td><td>Charge Done</td></tr>
<tr><td>11</td><td>VIN charger fault</td></tr>
</table></td></tr>
<tr><td>3</td><td>Reserved</td><td>R</td><td>This bit returns 0.</td></tr>
<tr><td>2:0</td><td>FAULT_V</td><td>R</td><td>Delineates VIN Charger Faults
Table 23. VIN Charger Fault Bits
<table>
<tr><th colspan="3">Bits</th><th rowspan="2">Charger Mode</th></tr>
<tr><th>2</th><th>1</th><th>0</th></tr>
<tr><td>0</td><td>0</td><td>0</td><td>Normal (no fault)</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>$V_{IN} > VIN_{OVP}$</td></tr>
<tr><td>0</td><td>1</td><td>0</td><td>Sleep Mode: $V_{IN} < V_{BAT}$</td></tr>
<tr><td>0</td><td>1</td><td>1</td><td>Poor VIN input source</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>Battery OVP</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>Thermal shutdown</td></tr>
<tr><td>1</td><td>1</td><td>0</td><td>Timer fault</td></tr>
<tr><td>1</td><td>1</td><td>1</td><td>No battery</td></tr>
</table></td></tr>
<tr><td colspan="3">CONTROL1_V</td><td>Reg Addr: 1 Slave Addr: D4 Default = 0111 0000</td></tr>
<tr><td>7:6</td><td>Reserved</td><td>R/W</td><td>These bits have no effect on IC operation. Input current is not limited by the IC when charging from VIN.</td></tr>
<tr><td>5:4</td><td>VLOWV_V</td><td>R/W</td><td><i>See Table 16. VLOWV: Weak Battery Threshold</i></td></tr>
<tr><td>3</td><td>TE_V</td><td>R/W</td><td>0: Charge termination is disabled when charging from VIN.
1: Charge termination is enabled for VIN charging.</td></tr>
<tr><td>2</td><td>CE#_V</td><td>R/W</td><td>0: VIN charger is enabled.
1: VIN charger is disabled. This bit is set when t_{15MIN} expires, regardless of which input source is charging.</td></tr>
<tr><td>1</td><td>HZ_V</td><td>R/W</td><td>0: VIN charger is not in High-Impedance Mode.
1: VIN charger is in High-Impedance Mode.</td></tr>
<tr><td>0</td><td>Reserved</td><td>R</td><td>This bit returns 0.</td></tr>
<tr><td colspan="3">OREG_V</td><td>Reg Addr: 2 Slave Addr: D4 Default = 0000 1010</td></tr>
<tr><td>7:2</td><td>OREGV</td><td>R/W</td><td>Charger output “float” voltage when charging from VIN source.
Programmable from 3.5 to 4.44 V in 20 mV increments. Defaults to 000010 (3.54 V) <i>(see Table 5)</i>.</td></tr>
<tr><td>1:0</td><td>Reserved</td><td>R</td><td>These bits return 10.</td></tr>
<tr><td colspan="3">IC_INFO_V</td><td>Reg Addr: 3 Slave Addr: D4 Default = 100x x000</td></tr>
<tr><td>7:5</td><td>VENDOR</td><td>R</td><td>100: Identifies Fairchild as the supplier.</td></tr>
<tr><td>4:3</td><td>PN_V</td><td>R</td><td>Part number bits: FAN54300 = 00</td></tr>
<tr><td>2:0</td><td>REV</td><td>R</td><td>IC Revision: Revision is 1.X, where X is the decimal of these 3 bits.</td></tr>
</table>

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td colspan="4">**IBAT_V** **Reg Addr: 4** **Slave Addr: D4 Default = 0000 0001**</td></tr>
<tr><td>7</td><td>RESETV</td><td>W</td><td>Writing a 1 resets all registers programmed with slave address D4, except the Safety register (Reg6), to their defaults. Writing a 0 has no effect. Read returns 0.</td></tr>
<tr><td>6:3</td><td>ICHGV</td><td>R/W</td><td>Sets the maximum charge current (I_{CHARGE}) when charging from VIN when IO_LEVELV = 0.
Table 24. I_{CHARGE} Current as a Function of the ICHGV Bits and R_{SENSE} Resistor Value
<table>
<tr><th rowspan="2">BIN</th><th rowspan="2">HEX</th><th rowspan="2">V_{RSENSE} (mV)</th><th colspan="2">$I_{OCHARGE}$ (mA)</th></tr>
<tr><th>68mΩ</th><th>100mΩ</th></tr>
<tr><td>**0000**</td><td>**00**</td><td>**37.4**</td><td>**550**</td><td>**374**</td></tr>
<tr><td>0001</td><td>01</td><td>44.2</td><td>650</td><td>442</td></tr>
<tr><td>0010</td><td>02</td><td>51.0</td><td>750</td><td>510</td></tr>
<tr><td>0011</td><td>03</td><td>57.8</td><td>850</td><td>578</td></tr>
<tr><td>0100</td><td>04</td><td>64.6</td><td>950</td><td>646</td></tr>
<tr><td>0101</td><td>05</td><td>71.4</td><td>1,050</td><td>714</td></tr>
<tr><td>0110</td><td>06</td><td>78.2</td><td>1,150</td><td>782</td></tr>
<tr><td>0111</td><td>07</td><td>85.0</td><td>1,250</td><td>850</td></tr>
<tr><td>1000</td><td>08</td><td>91.8</td><td>1,350</td><td>918</td></tr>
<tr><td>1001</td><td>09</td><td>98.6</td><td>1,450</td><td>986</td></tr>
<tr><td>1010</td><td>0A</td><td>105.4</td><td>1,550</td><td>1,054</td></tr>
</table>
Any attempt to write a value higher than 1010 results in ICHGV = 1010.</td></tr>
<tr><td>2:0</td><td>ITERMV</td><td>R/W</td><td>Sets the current at which charging terminates if the TE bit is set:
Table 25. I_{CHARGE} Termination Current as a Function of the ITERM bits and R_{SENSE} Resistor Value
<table>
<tr><th rowspan="2">BIN</th><th rowspan="2">HEX</th><th rowspan="2">V_{RSENSE} (mV)</th><th colspan="2">I_{TERM} (mA)</th></tr>
<tr><th>68mΩ</th><th>100mΩ</th></tr>
<tr><td>000</td><td>00</td><td>3.3</td><td>49</td><td>33</td></tr>
<tr><td>**001**</td><td>**01**</td><td>**6.6**</td><td>**97**</td><td>**66**</td></tr>
<tr><td>010</td><td>02</td><td>9.9</td><td>146</td><td>99</td></tr>
<tr><td>011</td><td>03</td><td>13.2</td><td>194</td><td>132</td></tr>
<tr><td>100</td><td>04</td><td>16.5</td><td>243</td><td>165</td></tr>
<tr><td>101</td><td>05</td><td>19.8</td><td>291</td><td>198</td></tr>
<tr><td>110</td><td>06</td><td>23.1</td><td>340</td><td>231</td></tr>
<tr><td>111</td><td>07</td><td>26.4</td><td>388</td><td>264</td></tr>
</table></td></tr>
</table>

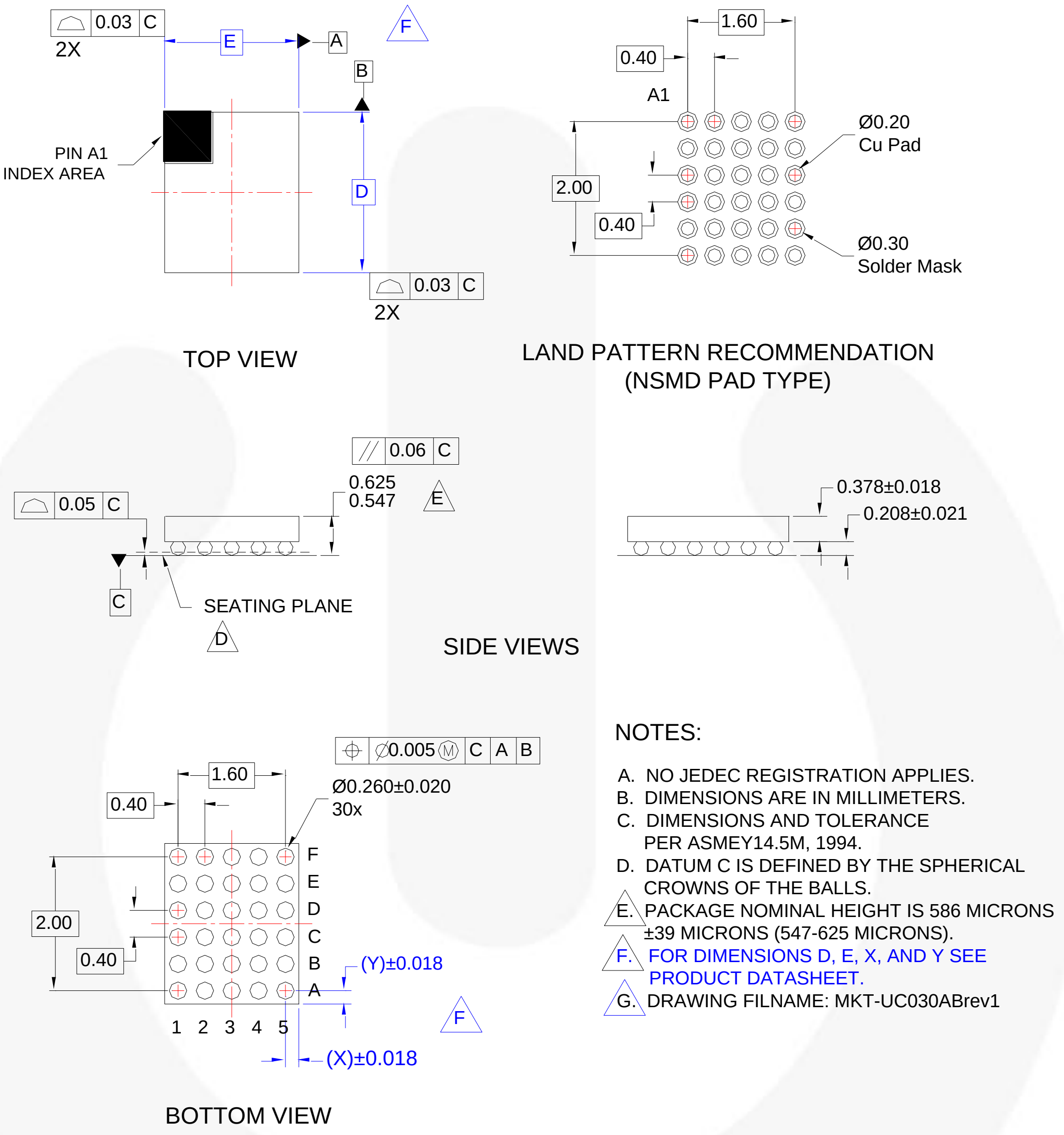
Bit	Name	Type	Description
SP_CHARGER_V			**Reg Addr: 5** **Slave Addr: D4 Default = 0x1x x100**
7	Reserved	R	This bit returns 0.
6	VIN_CON	R	Mirror of INPUT_STATUS[7] *(see INPUT_STATUS register description)*
5	IO_LEVELV	R/W	0: Output current is controlled by IOCHARGE bits for charging from VIN. When charging from VIN, the voltage across R_{SENSE} for output current control is set to 22.1mV (325mA for R_{SENSE} = 68mΩ, 221mA for 100mΩ).
4	SPV	R	Special charger loop is not active. V_{IN} is able to stay above V_{SP}. SPV = 0 when VIN is not PWM charging. 1: Special charger loop is active and controlling the charging current.
3	EN_LEVEL	R	0: DISABLE (DIS) pin is LOW. 1: DISABLE (DIS) pin is HIGH
2:0	VSPV	R/W	Sets the special charger control loop reference voltage when charging from VIN. If V_{IN} falls below this voltage, battery current is reduced until the input voltage is at or above V_{SP} *(see Table 19)*.

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td colspan="4">SAFE_V Reg Addr: 6 Slave Addr: D4 Default = 0100 0000</td></tr>
<tr><td>7:4</td><td>ISAFEV</td><td>R/W</td><td>Any attempt to write a value to ICHGV higher than the contents of ISAFEV sets ICHGV = ISAFEV. Any attempt to write a value higher than 1010 to ISAFEV results in ISAFEV = 1010.
Table 26. I_{CHARGE} Limit as a Function of the ISAFEV Bits when Charging from VIN
<table>
<tr><th rowspan="2">BIN</th><th rowspan="2">HEX</th><th rowspan="2">V_{RSENSE} (mV)</th><th colspan="2">I_{SAFE} (mA)</th></tr>
<tr><th>68mΩ</th><th>100mΩ</th></tr>
<tr><td>0000</td><td>00</td><td>37.4</td><td>550</td><td>374</td></tr>
<tr><td>0001</td><td>01</td><td>44.2</td><td>650</td><td>442</td></tr>
<tr><td>0010</td><td>02</td><td>51.0</td><td>750</td><td>510</td></tr>
<tr><td>0011</td><td>03</td><td>57.8</td><td>850</td><td>578</td></tr>
<tr><td>0100</td><td>04</td><td>64.6</td><td>950</td><td>646</td></tr>
<tr><td>0101</td><td>05</td><td>71.4</td><td>1,050</td><td>714</td></tr>
<tr><td>0110</td><td>06</td><td>78.2</td><td>1,150</td><td>782</td></tr>
<tr><td>0111</td><td>07</td><td>85.0</td><td>1,250</td><td>850</td></tr>
<tr><td>1000</td><td>08</td><td>91.8</td><td>1,350</td><td>918</td></tr>
<tr><td>1001</td><td>09</td><td>98.6</td><td>1,450</td><td>986</td></tr>
<tr><td>1010</td><td>0A</td><td>105.4</td><td>1,550</td><td>1,054</td></tr>
</table></td></tr>
<tr><td>3:0</td><td>VSAFEV</td><td>R/W</td><td>Any attempt to write a value to OREGV that is higher than the value in the Max OREG column below results in OREGV = Max OREG <i>(see Table 21)</i>.</td></tr>
</table>

<table>
<tr><th>Bit</th><th>Name</th><th>Type</th><th>Description</th></tr>
<tr><td colspan="4">LED_CONTROL Reg Addr: 7 Slave Addr: D4 or D6 Default = 1000 0010</td></tr>
<tr><td>7:6</td><td>I_LED</td><td>R/W</td><td>Sets LED behavior
Table 27. LED Control Bits
<table>
<tr><td>00</td><td>LED is off</td></tr>
<tr><td>01</td><td>LED current = 1.13 mA</td></tr>
<tr><td>10</td><td>LED current = 2.25mA</td></tr>
<tr><td>11</td><td>LED current = 4.50 mA</td></tr>
</table></td></tr>
<tr><td>5</td><td>Reserved</td><td>R</td><td>This bit returns 0.</td></tr>
<tr><td>4</td><td>LED_ON</td><td>R/W</td><td>0: LED is only active when charging.
1: LED is active regardless of charging status.</td></tr>
<tr><td>3:2</td><td>LED_TON</td><td>R/W</td><td>Sets LED blink t_{ON}
Table 28. LED ON-Time
<table>
<tr><td>00</td><td>131 ms</td></tr>
<tr><td>01</td><td>262 ms</td></tr>
<tr><td>10</td><td>524 ms</td></tr>
<tr><td>11</td><td>Constant ON</td></tr>
</table></td></tr>
<tr><td>1:0</td><td>LED_TOFF</td><td>R/W</td><td>Sets LED blink t_{OFF}
Table 29. LED OFF-Time
<table>
<tr><td>00</td><td>393 ms</td></tr>
<tr><td>01</td><td>786 ms</td></tr>
<tr><td>10</td><td>1573 ms</td></tr>
<tr><td>11</td><td>3146 ms</td></tr>
</table></td></tr>
</table>

Bit	Name	Type	Description
CHARGE_STATUS			**Reg Addr: 8** **Slave Addr: D4 or D6**
7	ITERM_CMP	R	0: If TE = 1, ($V_{CSIN} – V_{BAT}$) < V_{ITERM}. If TE = 0, ($V_{CSIN} – V_{BAT}$) < 1 mV. 1: If TE = 0, ($V_{CSIN} – V_{BAT}$) > V_{ITERM}. If TE = 0, ($V_{CSIN} – V_{BAT}$) > 1 mV.
6	T_120	R	0: The die temperature is below 120°C. 1: The die temperature is above 120°C.
5	ICHG	R	0: ICHARGE loop is controlling charge current (charger is in CC Mode). 1: ICHARGE loop is not controlling charge current.
4	IBUS	R	0: IBUS is limiting charge current. 1: IBUS loop is not controlling charge current. This bit always = 1 when charging from VIN.
3	CV	R	1 indicates that the constant-voltage loop (OREG) is controlling the charger and that all current limiting loops have released. Deglitched 32ms.
2	LINCHG	R	0: Charger is not in Linear Mode 1: Charger is in Linear Mode (V_{BAT} < V_{SHORT}).
1:0	Reserved	R	These bits always return 0.
INPUT_STATUS			**Reg Addr: 9** **Slave Addr: D4 or D6**
7	VIN_CON	R	0: V_{IN} has been less than V_{BAT} for at least 100ms (VIN is disconnected). 1: V_{IN} > V_{BAT} and V_{IN} > 4.5 V for at least 4ms (VIN is connected). This bit is mirrored in SP_CHARGER_U[3] and SP_CHARGER_V[6].
6	VIN_VALID	R	0: V_{IN} has not passed validation. 1: V_{IN} has passed validation and can be used as a charging source.
5	VBUS_CON	R	0: V_{BUS} has been less than V_{BAT} for at least 100ms (VBUS is disconnected). 1: V_{BUS} > V_{BAT} and V_{BUS} > 4.5 V for at least 4ms (VBUS is connected).
4	VBUS_VALID	R	0: V_{BUS} has not passed validation. 1: V_{BUS} has passed validation and can be used as a charging source. This bit is mirrored in SP_CHARGER_U[6].
3	SOURCE	R	0: V_{IN} is used for IC power and charging. 1: V_{BUS} is used for IC power and charging.
2:0	Reserved	R	These bits always return 0.

Physical Dimensions



NOTES:

A. NO JEDEC REGISTRATION APPLIES.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.
D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
G. DRAWING FILNAME: MKT-UC030ABrev1

Figure 61. 30-Ball, WLCSP, 5x6 Array, 0.4 mm Pitch, 586 µm Package Height

Product-Specific Dimensions

Product	D	E	X	Y
FAN54300UCX	2.460 ±0.030 mm	2.26 ±0.030 mm	0.330 mm	0.230 mm

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